

Service d'Electronique, Détecteurs, et Informatique (Irfu/SEDI)
Laboratoire Léon Brillouin (Iramis/LLB)

Neutron detectors based on the MICRO-Mesh Gaseous Structure (MICROMEAS)

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Contents

- Micromegas concept + technologies (bulk / microbulk)
- Neutron detection with Micromegas
- Multilayer concept *NMI3*
- 5 – layer prototype performance
- Towards *SINE2020* :
- Using Kapton meshes
- Implementing microbulk technology to have a stack
- Simulations – design – build of a prototype
- Summary + future plans

Micromegas concept

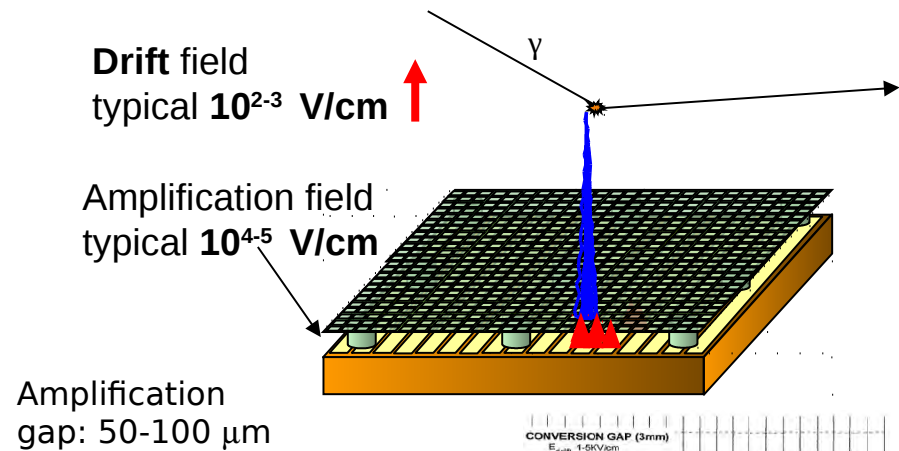
Two-region gaseous detector
separated by a Micromesh :

- Conversion region
- Amplification region

- Primary ionization
- Charge drift towards A.R.
- Charge multiplication
- Readout layout
 - Strips (1/2 D)
 - Pixels

□ Very strong and uniform electric field

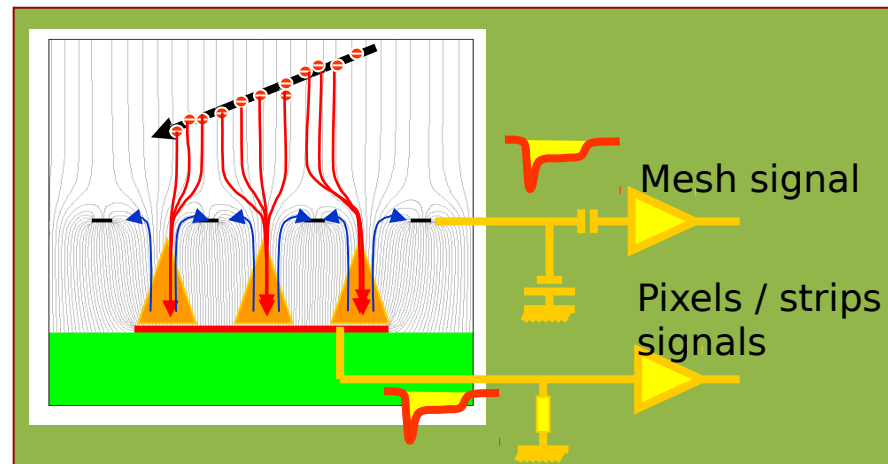
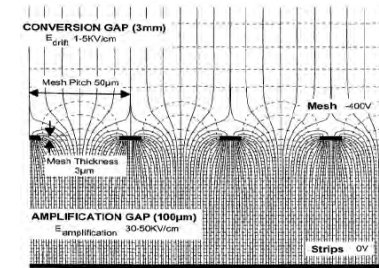
- metallic micromesh (typical pitch 50µm)
- sustained by 50-100 µm pillars
- simplicity
- single stage of amplification
- fast and natural ion collection
- discharges non destructive



MICROMesh Gaseous Structure
Giomataris, Charpak (1996)

Y. Giomataris *et al.*, NIM A 376 (1996) 29

In 1st Micromegas
Fishing line spacers have been used



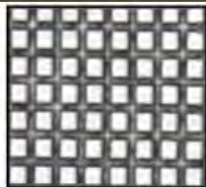
MICROMEGAS description + technologies (i)

Micro-mesh (cathode)

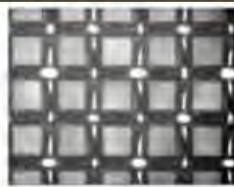
The metallic micro-mesh must be 5 to 30 μm thick with needed equivalent wires densities ranging from 500 to 2000 Lines Per Inch (LPI). Stainless steel woven meshes, electroformed Nickel meshes, or chemically etched copper meshes are used.

New products are needed for high LPI thin meshes.

500 LPI Electroformed Ni mesh



500 LPI 304L woven mesh

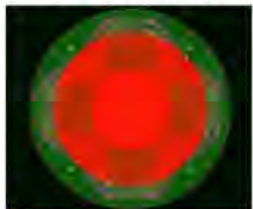


Chemically etched Copper mesh



Printed Circuit Board (anode PCB)

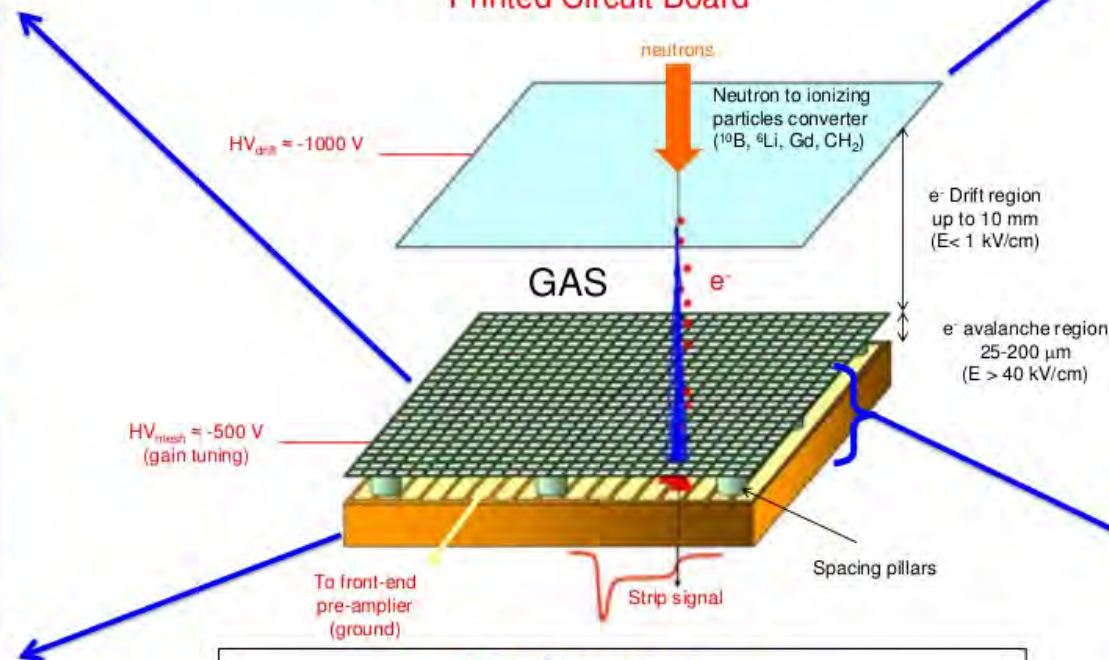
- ✓ It can be up to 1-3 m^2 and down to 100 μm thin.
- ✓ Copper strips or pads can be $\approx 100 \mu\text{m}$ to few mm large and insulation between them as low as 50 μm .
- ✓ Copper is usually covered by a Ni/Au layer for a total thickness which must be kept as low as possible (down to 5 μm) with a « smooth » surface.



A $\Phi 30 \text{ cm}$ 12 layers PCB with $4000 \times 4 \text{ mm}^2$ pads for the MINOS TPC (18000 blind vias)

Patented technology (CEA – EOS imaging)
G. Charpak, Y. Giomataris, Ph. Rebougeard, J-P Robert
Y. Giomataris *et al.*, NIM A 376 (1996) 29

MICROMEGAS is a parallel plate gaseous structure which uses a **thin metallic micromesh** to define the high electric field region in which primary electrons are amplified by avalanche and collected on a **micro-segmented Printed Circuit Board**



Performances

- ✓ Intrinsic low sensitivity to γ photons (gas)
- ✓ High spatial resolution (down to 100 μm)
- ✓ Fast signals ($< 1 \text{ ns}$)
- ✓ Short recovery time ($\sim 150 \text{ ns}$)
- ✓ High rate capabilities ($> \text{MHz}$)
- ✓ High gain (up to 10^6)

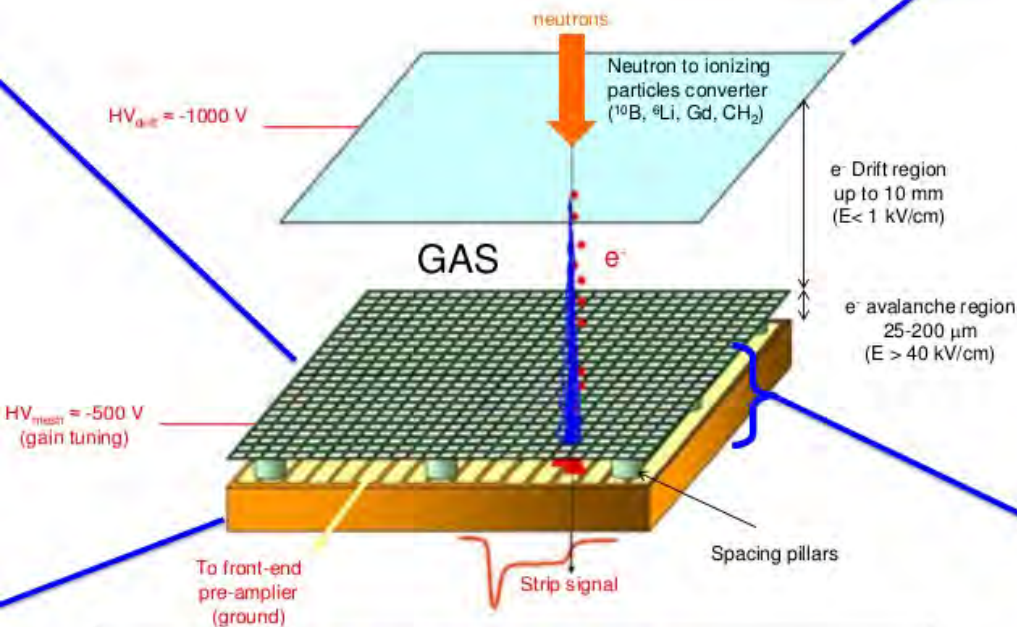
MICROMEGAS description + technologies (ii)

Patented technology (CEA – EOS imaging)

G. Charpak, Y. Giomataris, Ph. Rebougeard, J-P Robert

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MICROMEGAS is a parallel plate gaseous structure which uses a **thin metallic micromesh** to define the high electric field region in which primary electrons are amplified by avalanche and collected on a **micro-segmented Printed Circuit Board**



Performances

- ✓ Intrinsic low sensitivity to γ photons (gas)
- ✓ High spatial resolution (down to 100 μm)
- ✓ Fast signals (< 1 ns)
- ✓ Short recovery time (~ 150 ns)
- ✓ High rate capabilities (> MHz)
- ✓ High gain (up to 10^6)

Drift electrode + neutron converter

- ✓ For **thermal neutrons**, it can be a thin aluminum foil or a metallic mesh covered by a 1-2 μm thick layer containing ^{10}B (such as B_4C) or by a ≈ 100 μm thick ^6Li layer.

An electroformed Ni mesh covered by a 2 μm thick B_4C layer (Linköping Univ.)

Low cost industrialized processes needed

- ✓ For **high energy neutrons**, a few mm thick polyethylene (CH_2) sheet is used.



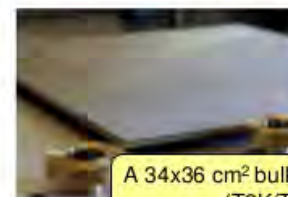
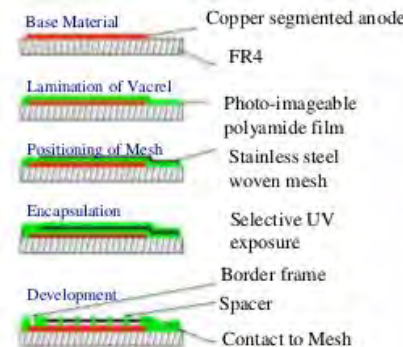
Micromegas technologies

to realize the micro-mesh + anode PCB assembly

Bulk-micromegas

On-going technology transfer

Embedding of the mesh between two layers of insulating pillars by use of photolithography technics



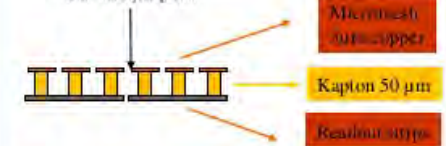
A 34x36 cm² bulk-micromegas (T2K/TPC)

micro-bulk micromegas

Technology transfer to be done

Micromegas is built from a double sided copper clad kapton foil by selective chemical etching of copper (mesh and anode strips) and kapton (insulating pillars).

Mesh with typical $\Phi 40$ μm hole with 100 μm pitch



A 10x10 cm² micro-bulk (NEXT prototype)



Neutron detection with Micromegas

Neutron detection □ neutron to charge converter

- Solid converter: thin layers deposited on the drift or mesh electrode (^{10}B , $^{10}\text{B}_4\text{C}$, ^6Li , ^6LiF , U, actinides...)
 - ✓ Sample availability & handling
 - ✓ Efficiency estimation
 - ✗ *Limitation on sample thickness from fragment range*
⇒ *limited efficiency*
 - ✗ Not easy to record all fragments
- Detector gas (^3He , BF_3 ...)
 - ✓ Record all fragments
 - ✓ No energy loss for fragments ⇒ reaction kinematics
 - ✓ No limitation on the size ⇒ high efficiency
 - ✗ *Gas availability*
 - ✗ Handling (highly toxic or radioactive gasses)
- Neutron elastic scattering
 - gas (H, He)
 - solid (paraffin etc.)
 - ✓ Availability
 - ✓ High energies
 - ✗ Efficiency estimation & reaction kinematics

Neutron detection with high efficiency (~50%):

- ^3He crisis
- Increased demand for neutron detectors
 - ➔ Science
 - ➔ Homeland security
 - ➔ Industry

Micromegas for neutrons

- Micro-Pattern Gaseous Detector (gain, fast timing, high rate, granularity, radiation hardness, simplicity...)
- Low mass budget
- Transparent to neutrons
- Large area detectors cheap & robust

Ingredients to build a simple counter

Gained lots of experience in Boron deposition

- Simple method with B powder @ SEDI (Patrick Magnier)
- Electrodeposition, Sputtering @ DRT (Ph. Bergonzo Lab)
- Collaboration with DRT & Linköping University

Detector very interesting as a simple, portable, neutron counter for several facilities (i.e. LICORNE)

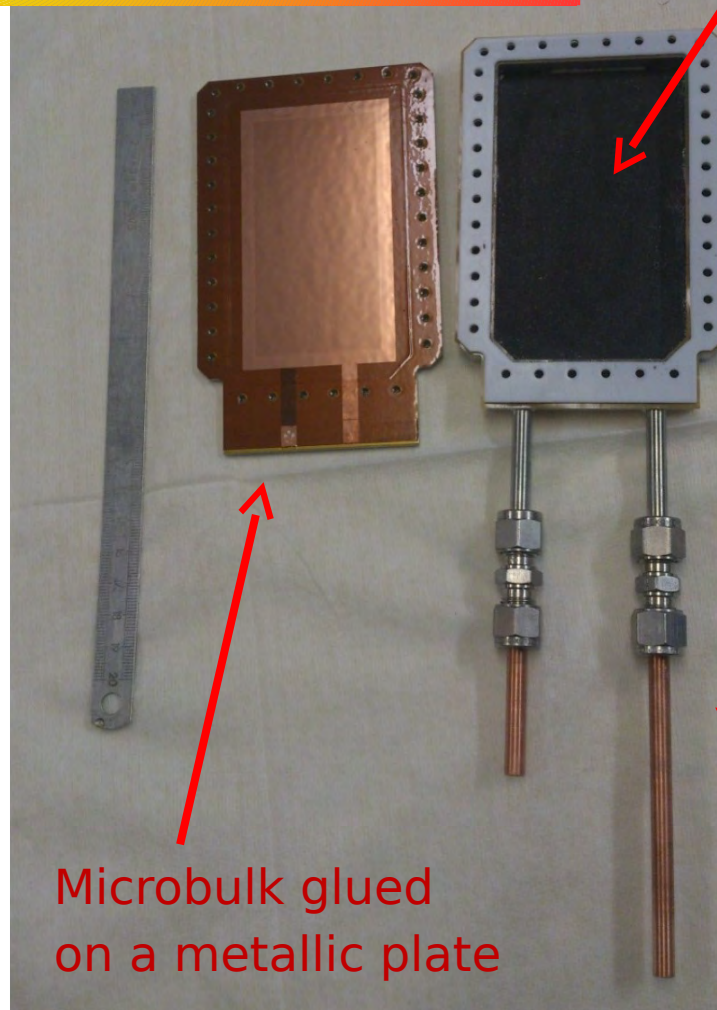
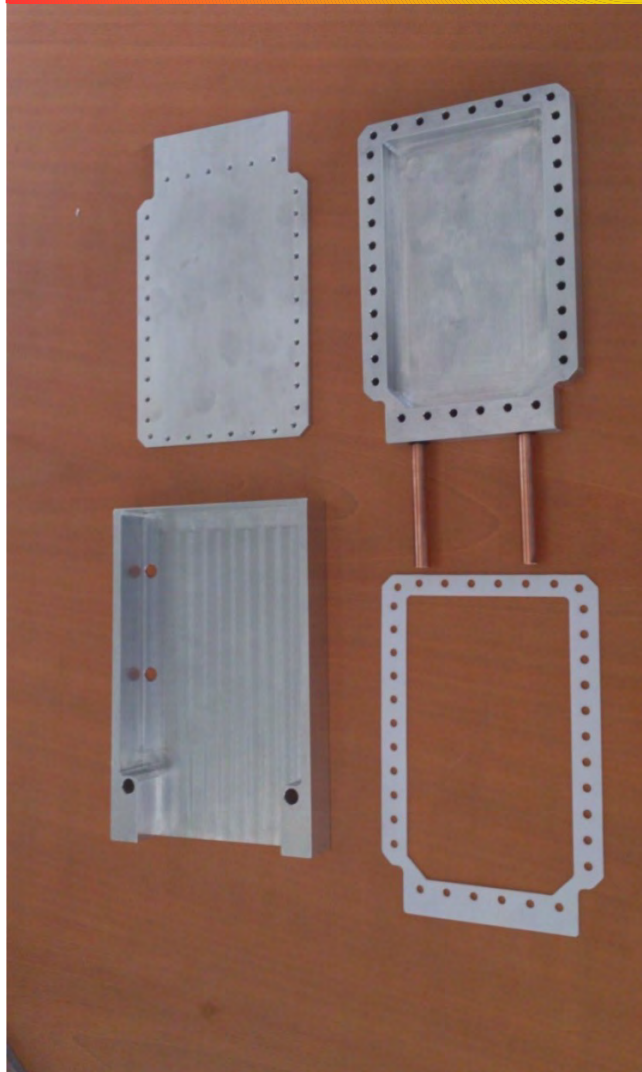
^{10}B layer (thick!) deposited on the inner part of the chamber

The ^{10}B layer is the less trivial part to build

- Material availability
- Deposition method
 - ✓ Sputtering
 - ✓ Evaporation
 - ✓ Electrodeposition
 - ✓ ...

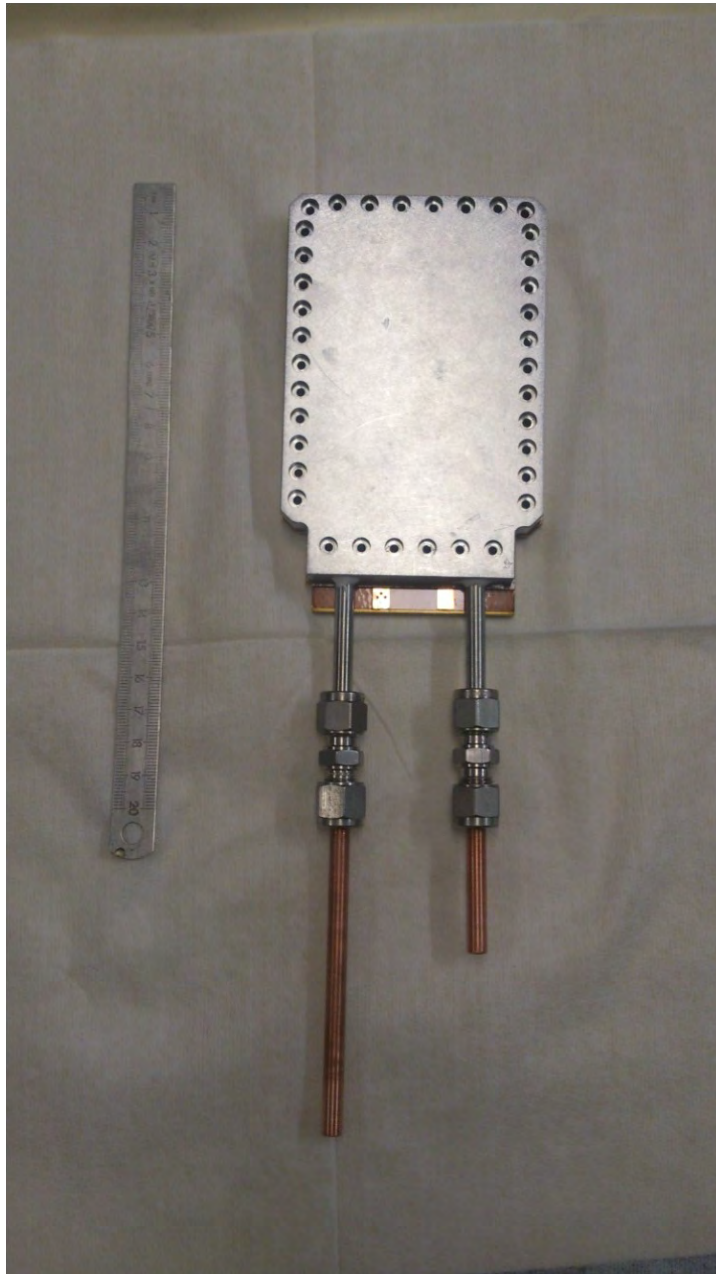
Teflon / kapton joint

Gas tubes



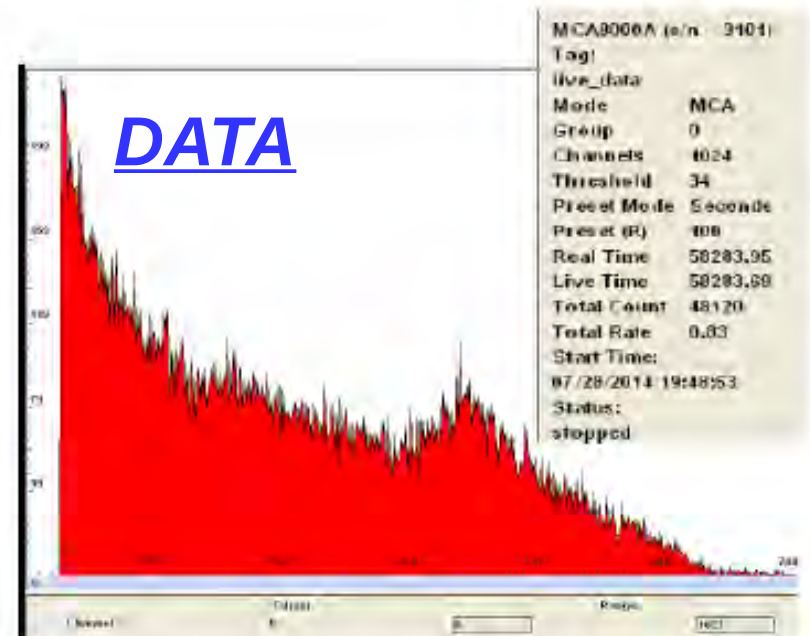
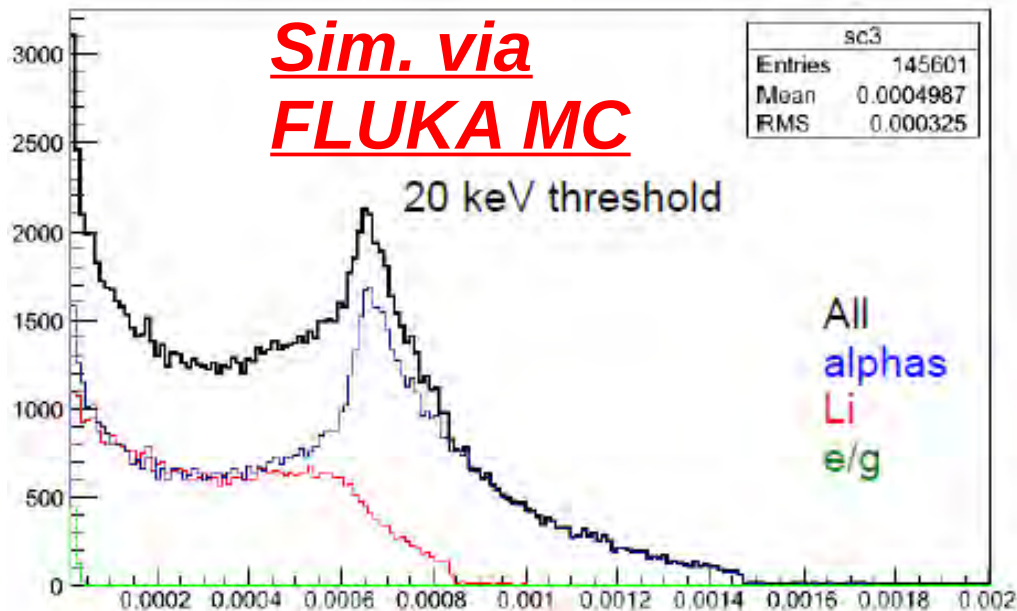
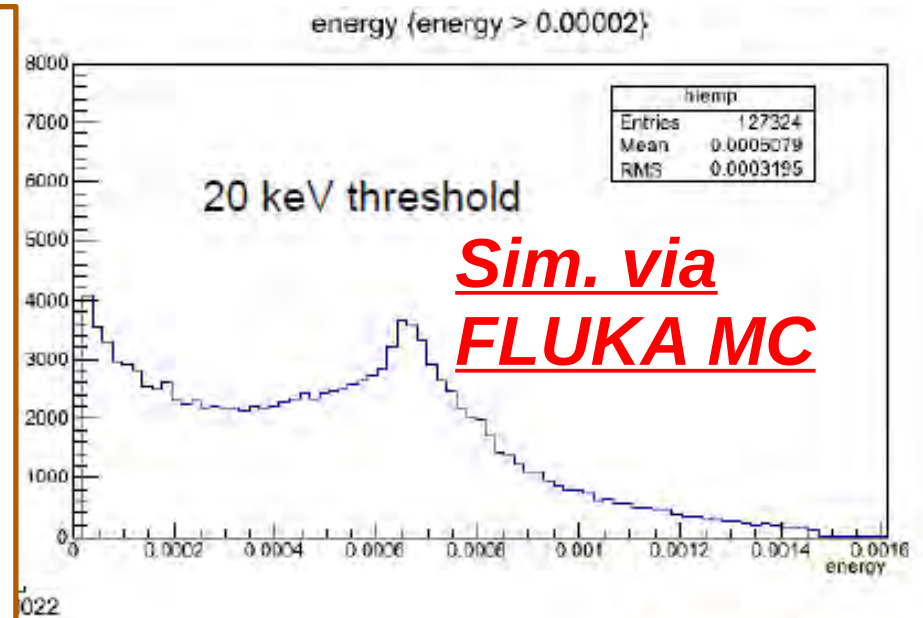
Microbulk glued on a metallic plate

The Schlumberger neutron counter



Performance

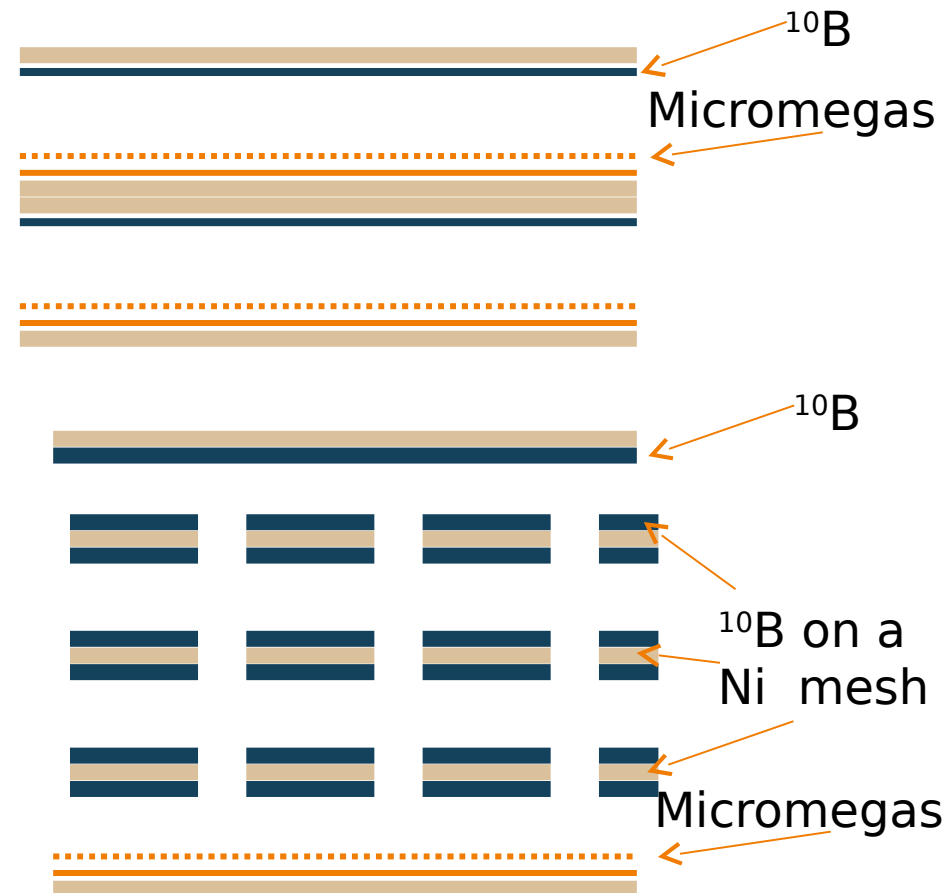
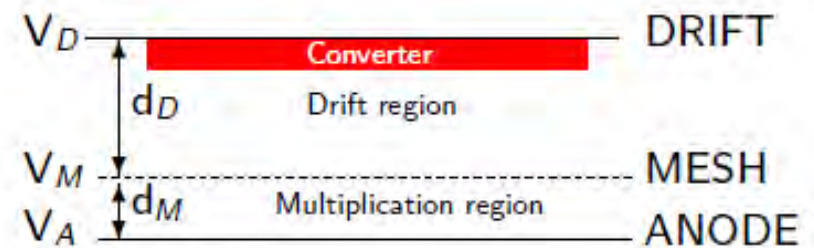
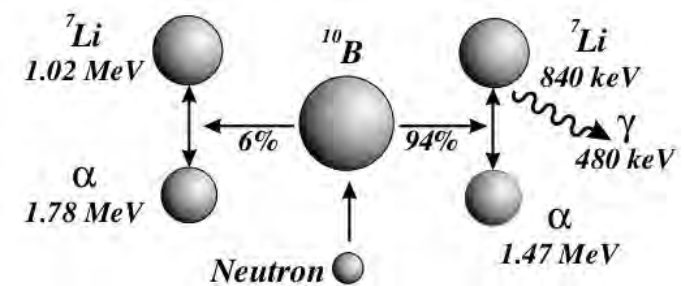
- 2 High voltages (+300V & +500V) for the mesh and the anode
- Single readout channel
- Operation in sealed mode (since July) – no gain loss
- *Measured efficiency: 4.3 - 5 % (reference ^3He tube)*



The multilayer concept (i)

- A boron layer thicker than **1-2 μm** is **not efficient** due to the **absorption** of the reaction products
- Maximum efficiency that can be achieved in this case is of the order of **4-5 %**
- ✓ One solution: a tower of detector-converter layers
 - ➔ Many detectors
 - ➔ Lots of material
- ✓ Alternative: a tower of converter layers for each detector: ^{10}B deposited on thin metallic meshes
 - ➔ Less electronics
 - ➔ Less material

Difficulty: drift the produced charges to the detector through the mesh holes (proper configuration of the electric field)



The multilayer concept (ii)

- One module can be consisted of a double-face Micromegas facing $7+7$ ^{10}B layers
- Such a module can be ~ 1 cm thick!
- Material:
 - ✓ $0.2 - 0.3 \text{ } \mu\text{m}$ PCB
 - ✓ $6 \times 5 \text{ } \mu\text{m}$ Ni
 - ✓ 2 x micromesh
 - ✓ 2 x 1 mm Aluminum case
- A stack of such detectors can be used to increase efficiency
- Detector can be tilted by 45° in respect to the neutron direction.

Status:

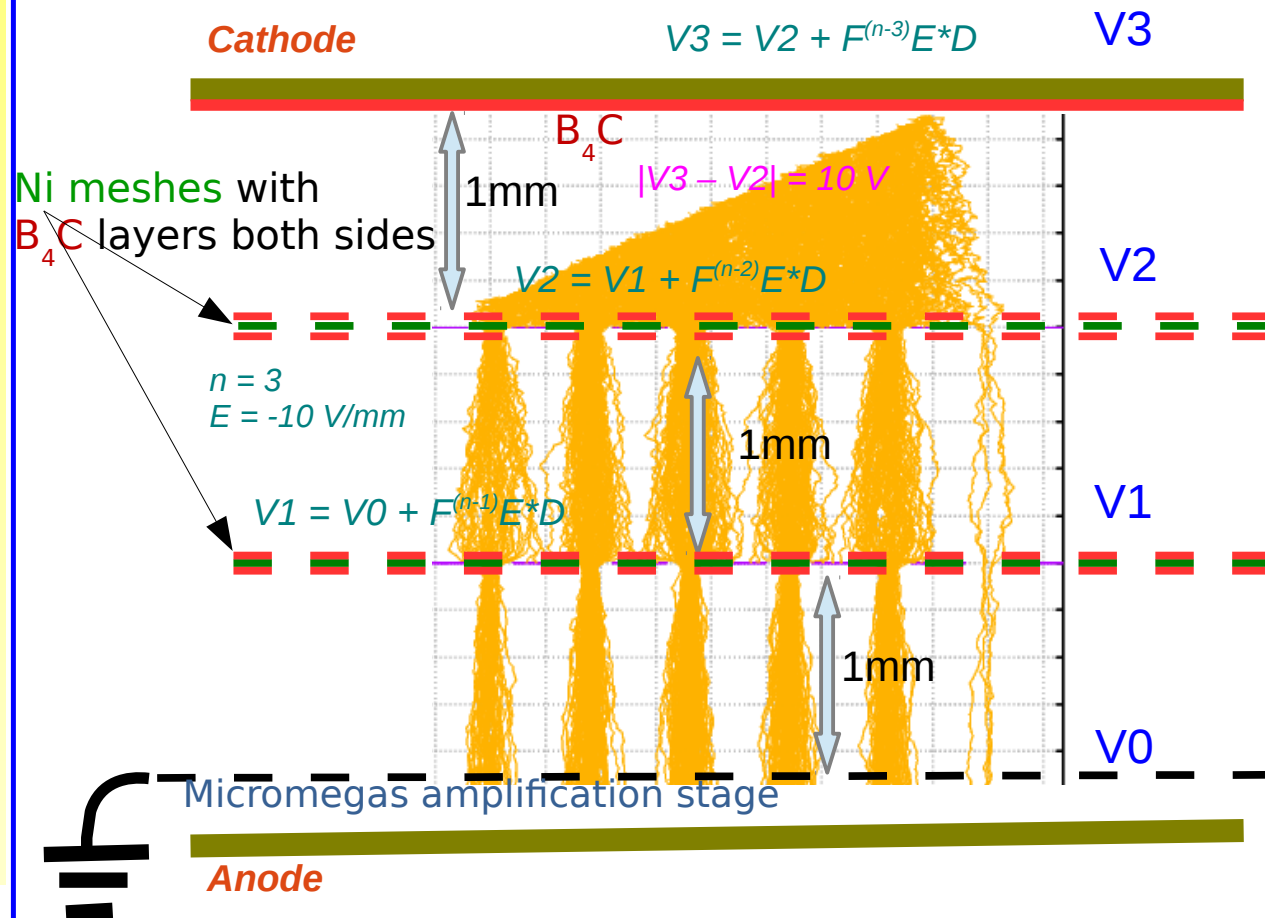
- *Monte-Carlo studies to optimize the electron transmission & sample thickness*
- *Prototype for performance studies*



Concept

- Use developments of Micromegas technology in Saclay to demonstrate the feasibility of a large high-efficiency neutron detector with several $^{10}\text{B}_4\text{C}$ thin layers mounted inside the gas volume.
- Built a single detector unit prototype with overall dimension of $\sim 15 \times 15 \text{ cm}^2$ and a flexibility of modifying the number of layers of $^{10}\text{B}_4\text{C}$ neutron converters.
- Evaluate *bulk* (NMI3) / *microbulk* (SINE2020) technologies for the construction of large sizes detectors made a mosaic of such detectors.

Micromegas neutron detector

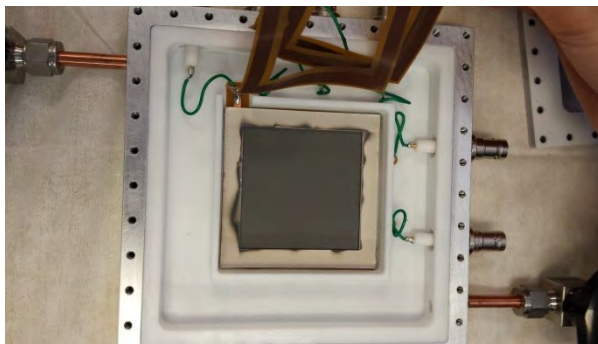
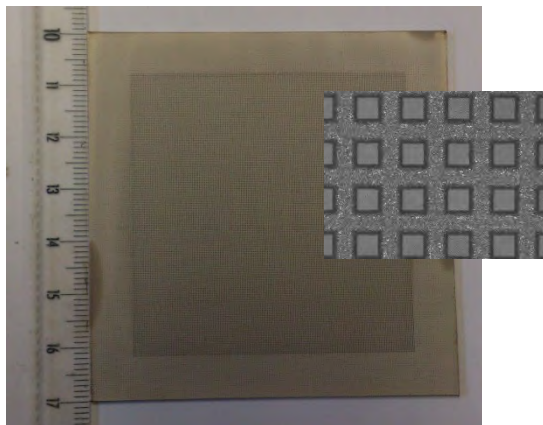
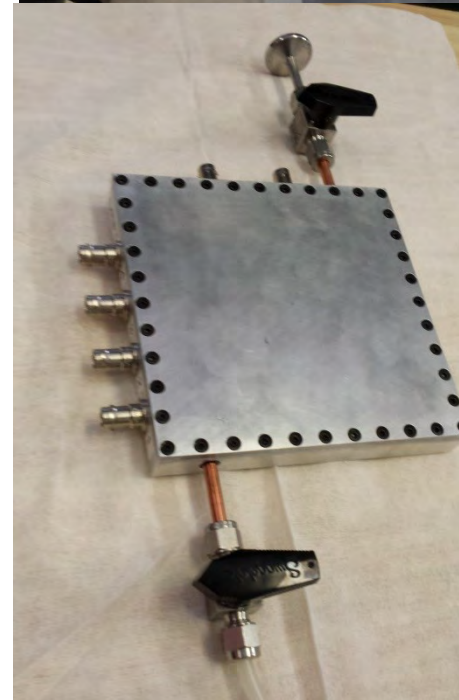
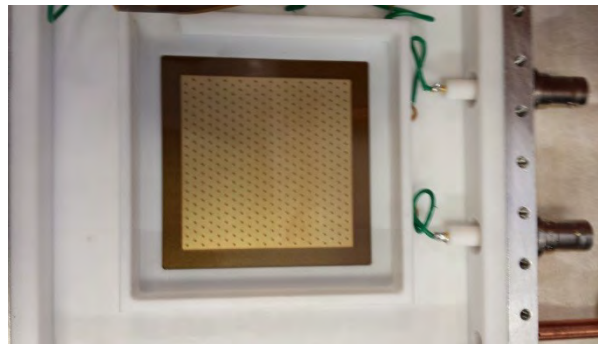
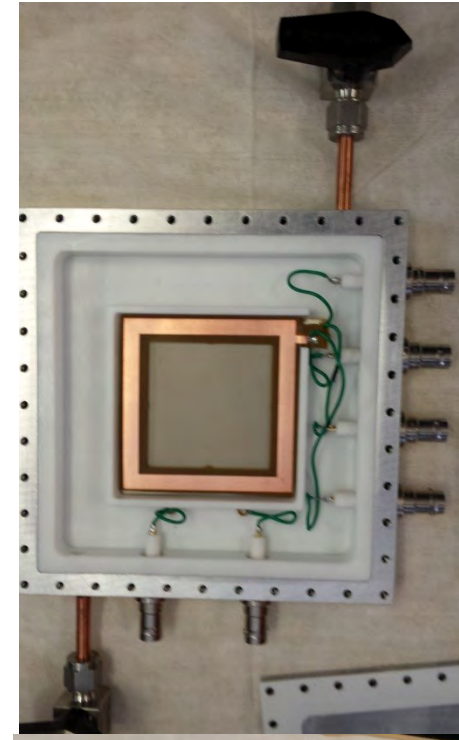


The NMI3 prototype

- Bulk Micromegas 5x5 cm²
- Ni frames 7x7 cm²
- Ni meshes 10% & 20% transparent
- Voltages applied with the help of kapton+Cu frames

Ni meshes double coated with 1.5 μm B₄C layers

- 10% - 20% transparent
- 5, 20, 120 μm thick
- 50, 100, 500, 1000 LPI
- (Linköping University)



Detection efficiency – FLUKA MC (i)

Simplified geometry of a Micromegas prototype

2 mesh of Nickel: 4 μm

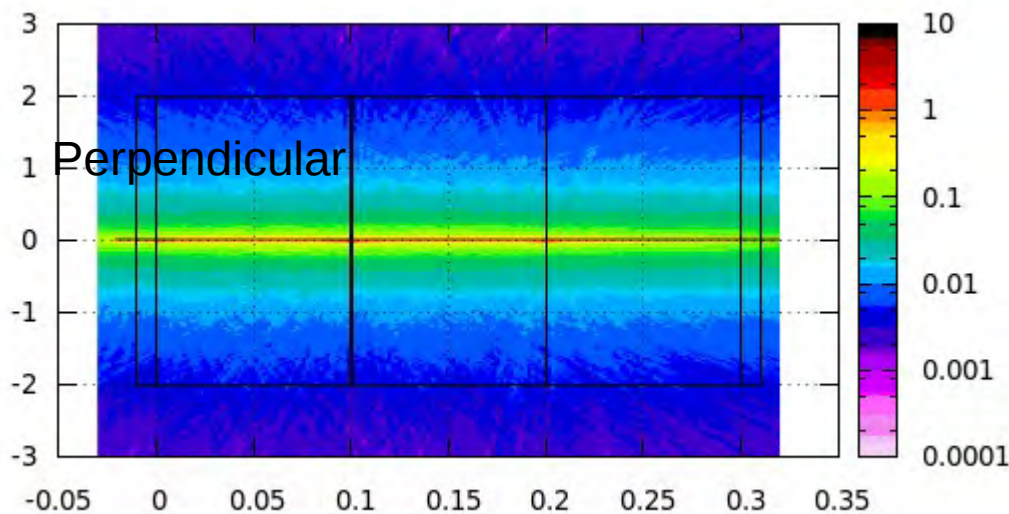
3 Gas layers CF_4 : 1-2-5 mm

5 layers of converter B_4C : 2 μm

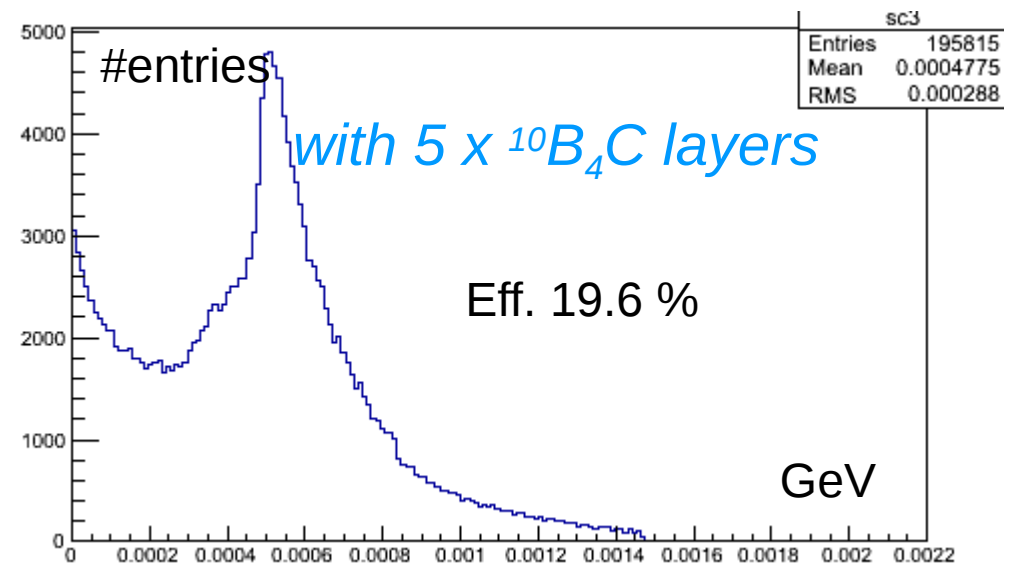
Neutron beam of 25 meV pencil-like parallel to z-axis

Energy Deposition is scored at the gas volumes

Calculated efficiency of detection : **19.6%**



Spatial distribution of ALL-PART fluence (tracklength density)
normalized to particles/cm²/primary

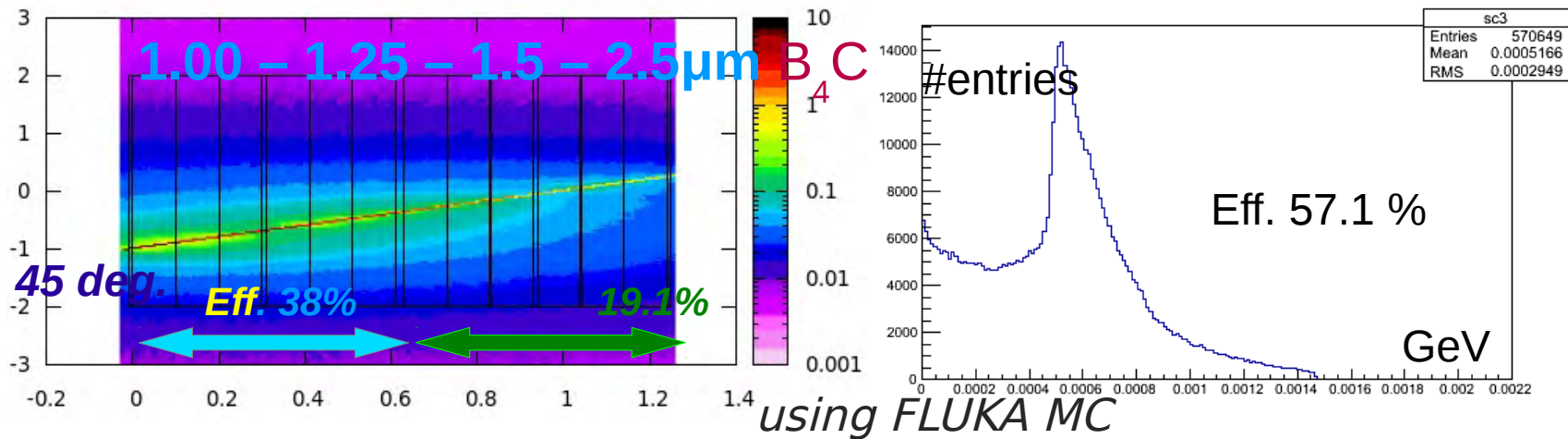


using FLUKA MC

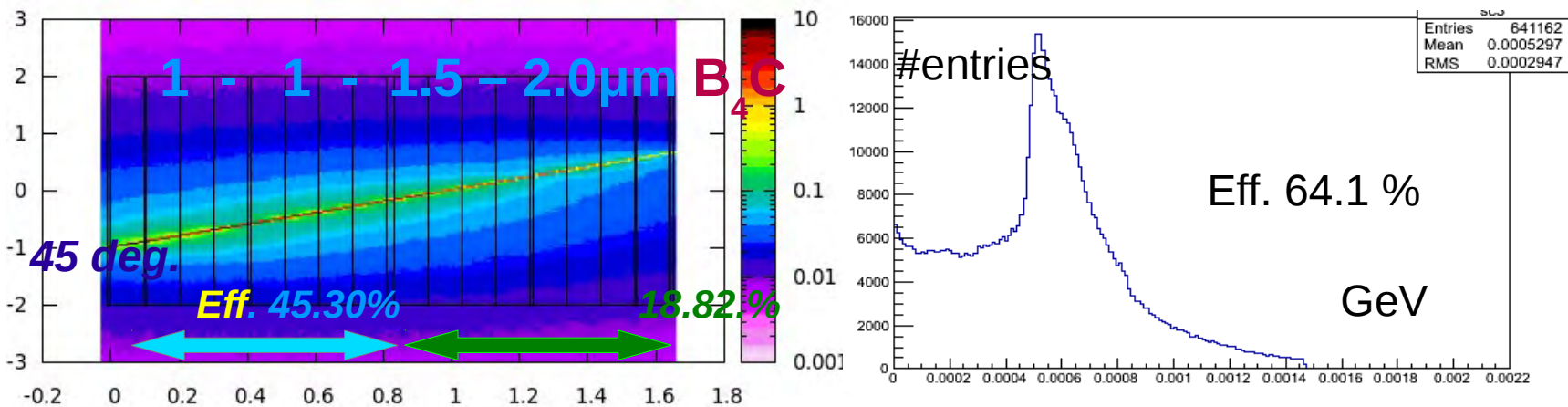
Detection efficiency – FLUKA MC (ii)

A >50% thermal neutron efficiency is reached with a 2 cm stack of transfer meshes with B₄C layers on both sides, and a proper electric field configuration

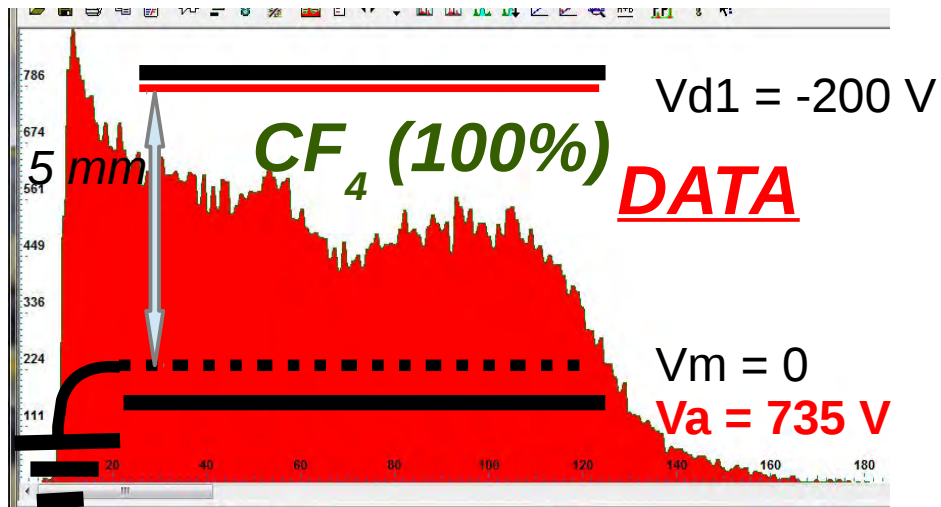
A “2-double 2-mesh detector unit” (20 B₄C layers)



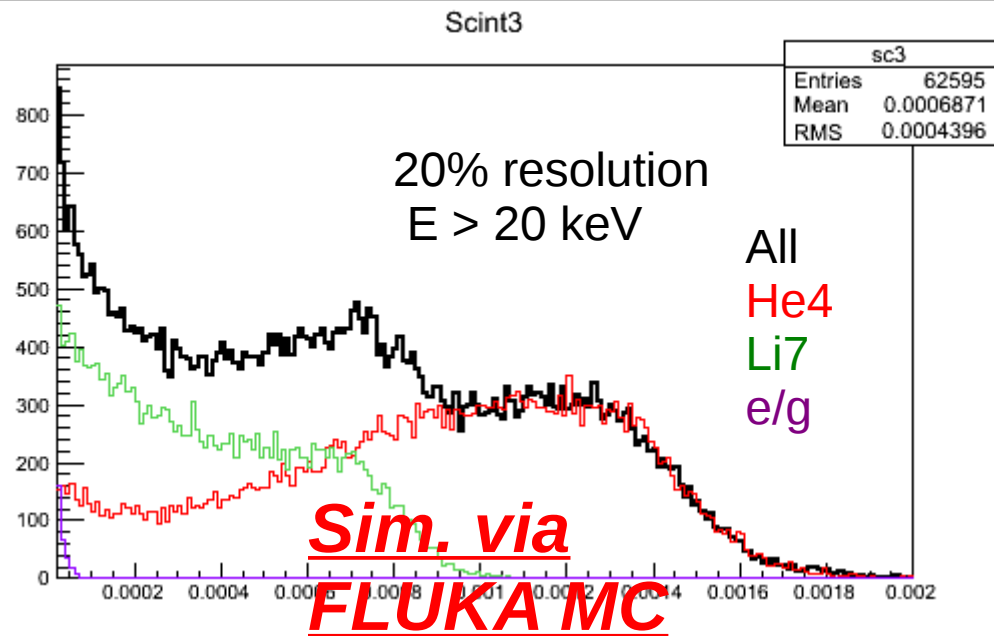
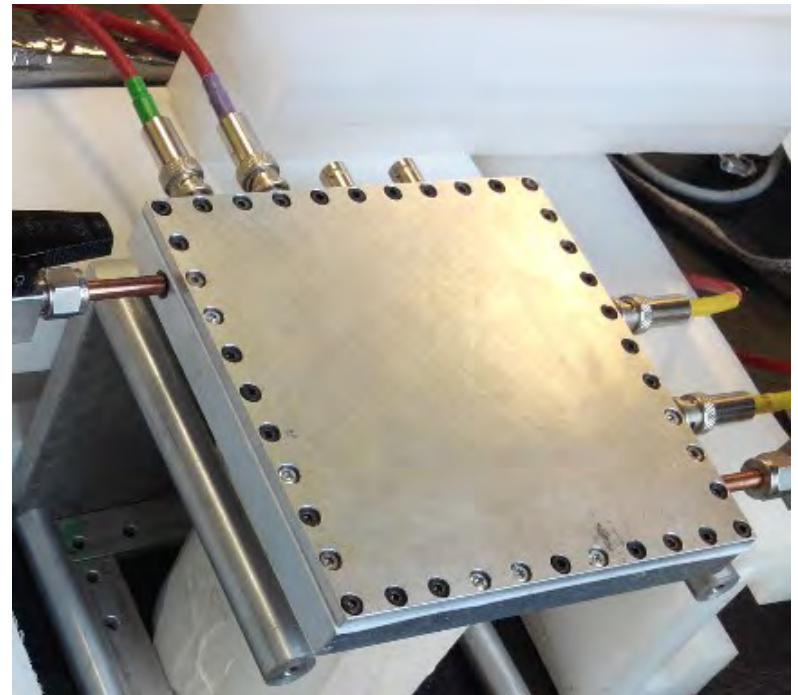
A “2-double 3-mesh detector unit” (28 B₄C layers)

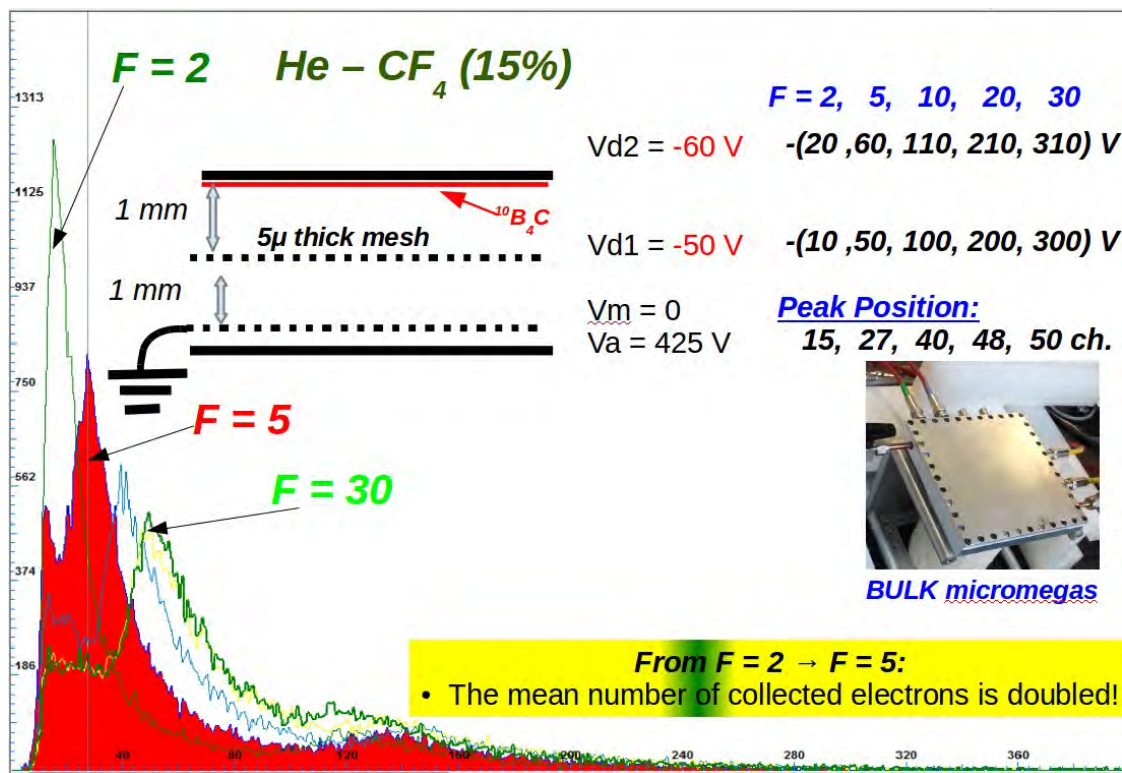


Measurements / simulations

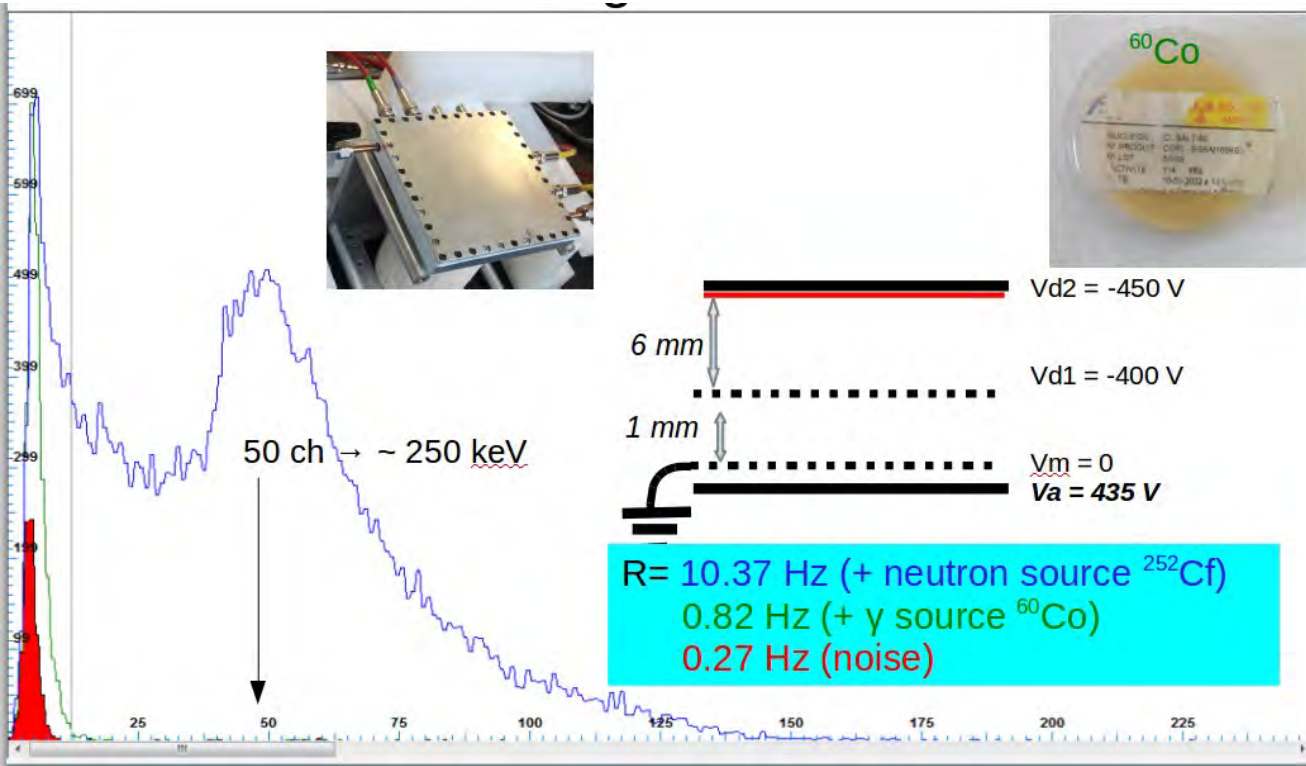


Cf-252 source
Total Rate ~ 13.16 Hz

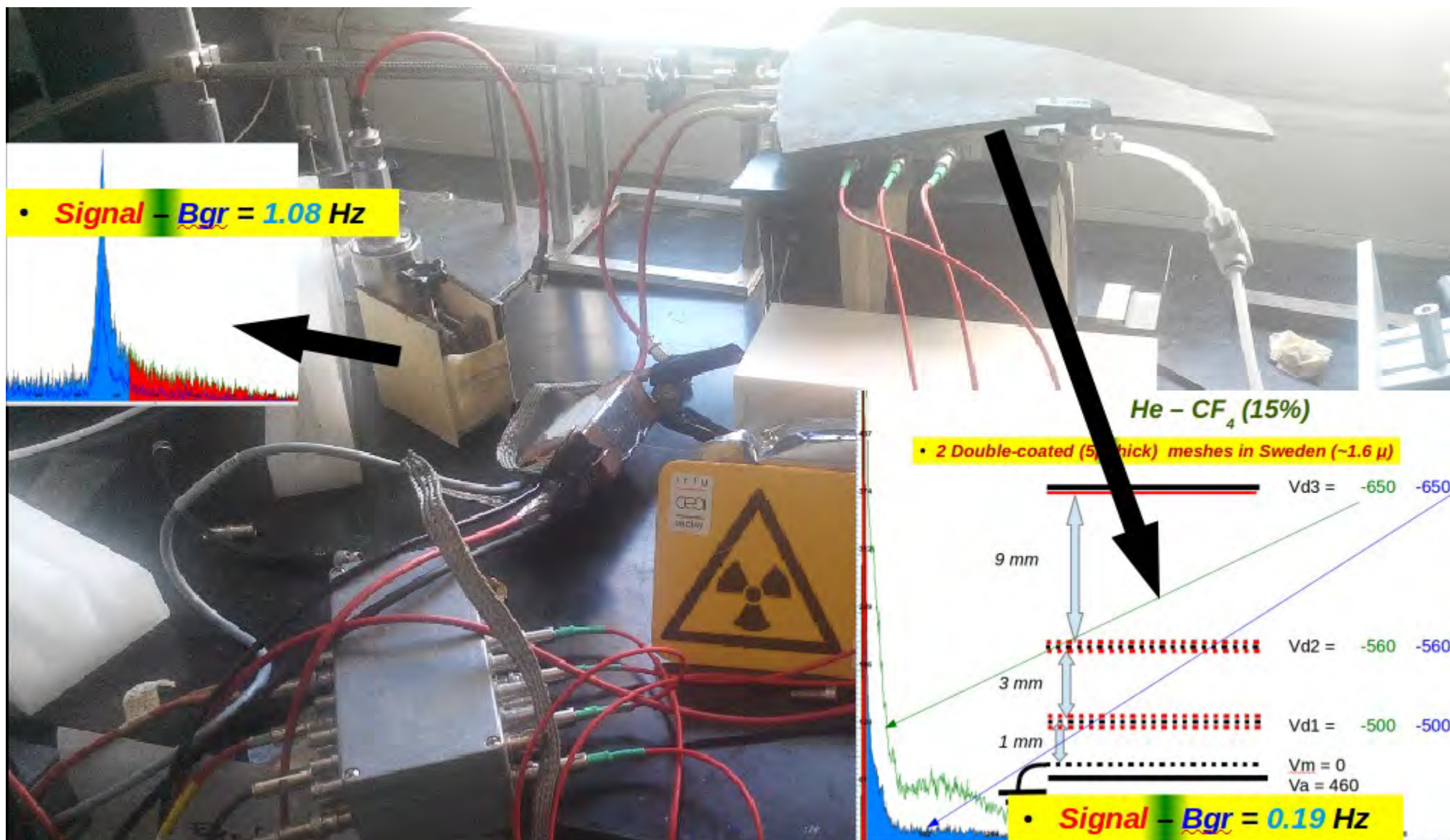




Data measured during 3000 s for each run for a field factor $F = [2, 5, 10, 20, 30]$ to get the collected electrons from the single-coated aluminium end plate.



Data measured during 3000 s for each run, using a neutron source ^{252}Cf , a gamma source ^{60}Co and without any source in order to evaluate the level of the electronic noise and the contamination from gammas, on a single detector unit equipped with a B 4 C single-coated aluminium end plate and two drift regions separated by a Ni mesh.



Evaluation of the thermal neutron detection efficiency of a single 2-mesh detector unit equipped with 5 layers of B₄C (right), compared to a 3 He tube detector (left).

5-layer prototype performance

A single 2-mesh detector unit → $F=7$, $5 \times B_4C$ layers

Comparison with commercial ^3He tube:

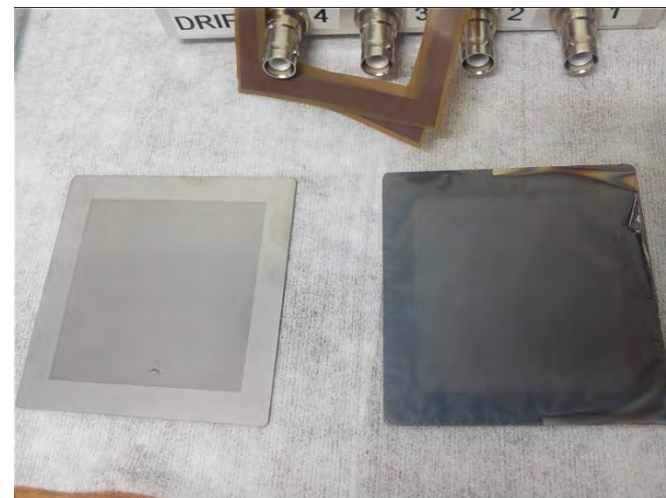
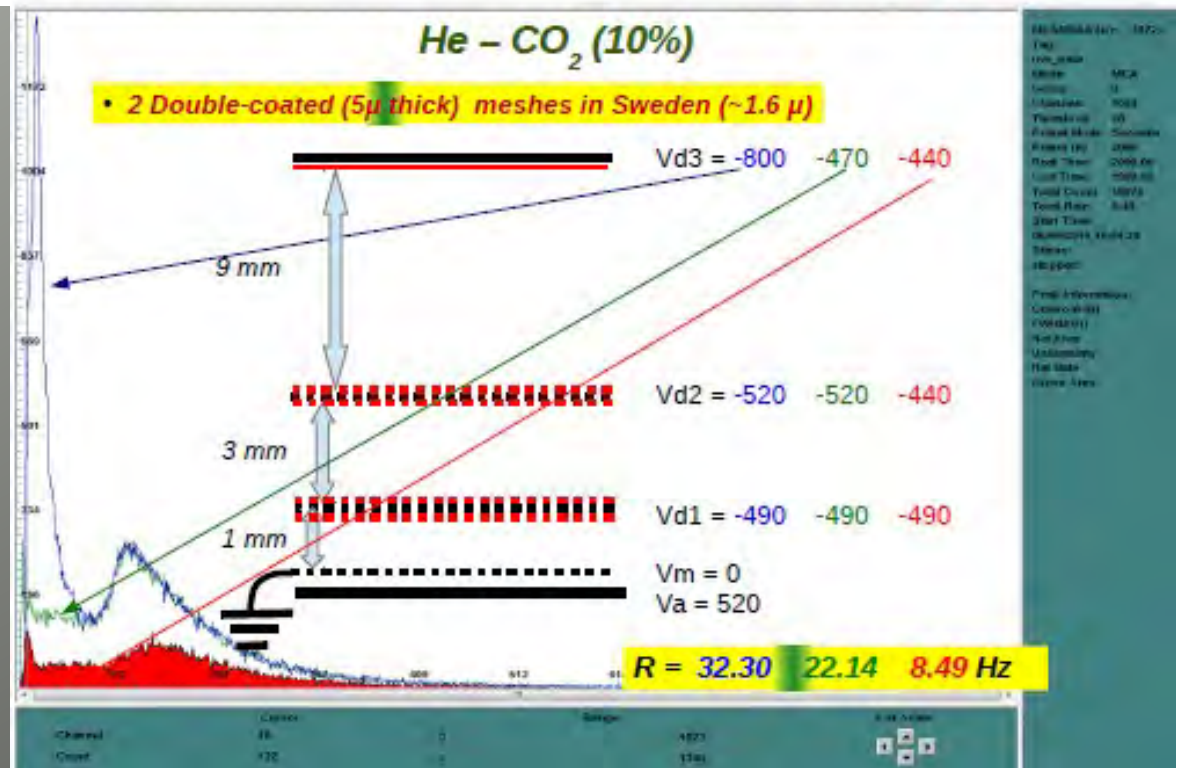
Count rate $\{^3\text{He} / \text{MM}\} = 5.5$
 Assuming ^3He eff. $\sim 95\%$
 → **MM eff $\sim 18\%$**

Satisfactory result

but:

- **Electron transmission too low when mesh thickness $\gg 5 \mu\text{m}$**
- **Mesh deformed during B_4C deposition if thickness $\ll 20 \mu\text{m}$**

□ *Difficult to operate with more than 3 layers per unit with large area Ni meshes*



Alternative 1: Kapton mesh (GEM-type)

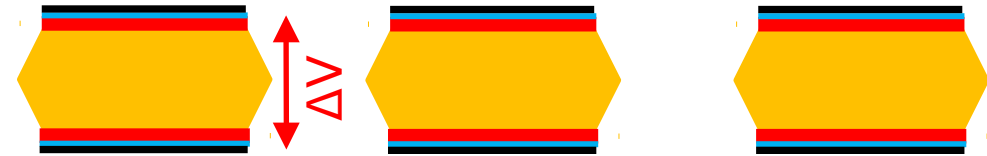
12.5 μm Kapton mesh

- double-side coated with 3-4 μm Cu
- double-side coated with 1 μm Ni
- double-side coated with 1.5 μm B_4C

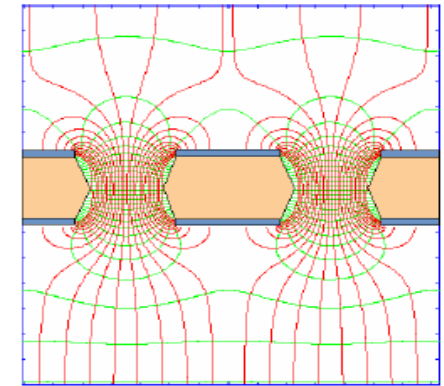
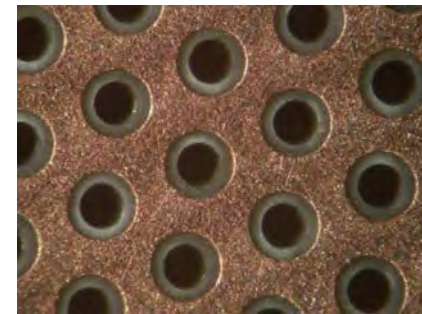
ΔV (10-50 V) applied between the two Cu layers
 \square electric field strong enough for sufficient electron transmission

- Small voltage for top layer (< 500 V)
- Small amplification possible to compensate electron losses (*factor 2-3*)

- ✓ **Mesh is cheap and robust**
- ✓ **Big surfaces possible ($1 \times 0.5 \text{ m}^2$)**

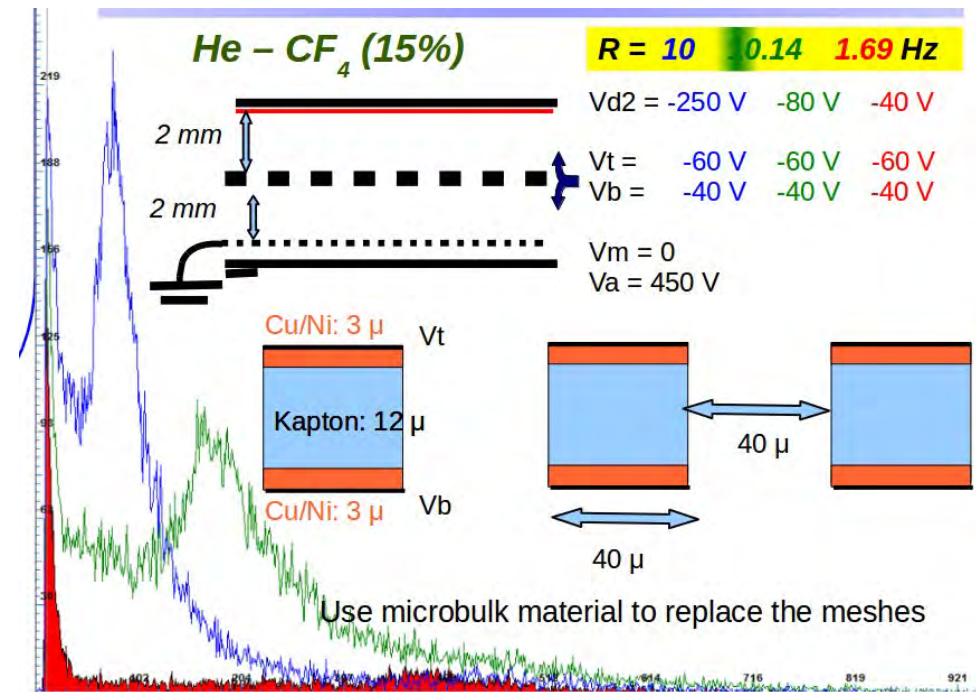


GEM-type kapton mesh



Problem with $^{10}\text{B}_4\text{C}$ deposition: thermal expansion.

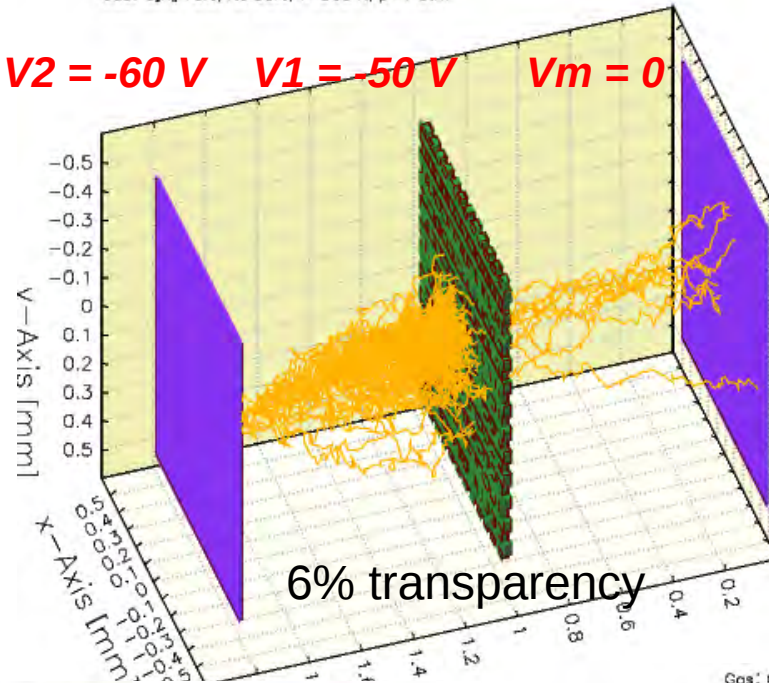
- Use pure ^{10}B
- Use a transparent mask (micromesh) during deposition of B_4C



Simulation / box model (garfield-nebem)

Gas: C_2H_6 10%, Ne 90%, $T=300$ K, $p=1$ atm

$V_2 = -60$ V $V_1 = -50$ V $V_m = 0$

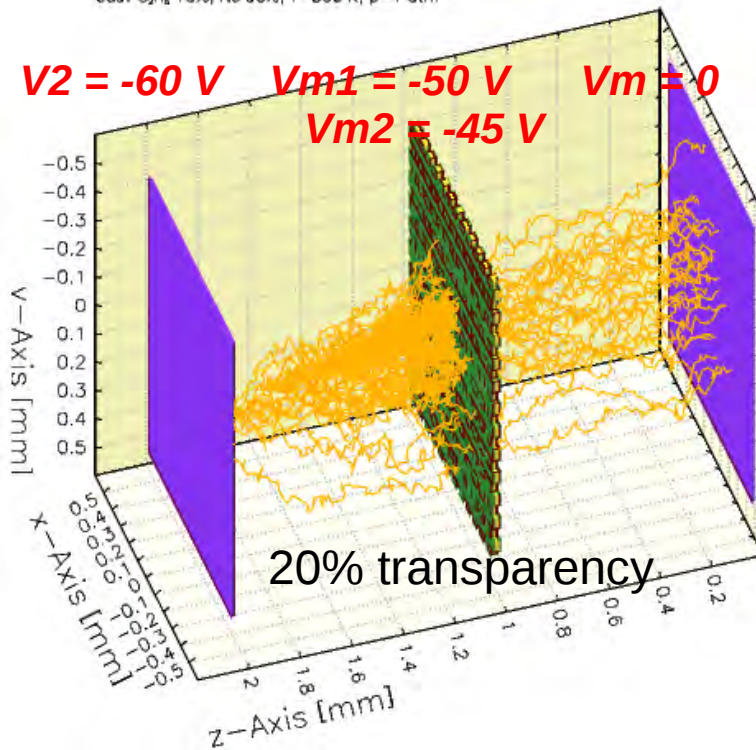


6% transparency

Ne - C_2H_6 (10%)

Gas: C_2H_6 10%, Ne 90%, $T=300$ K, $p=1$ atm

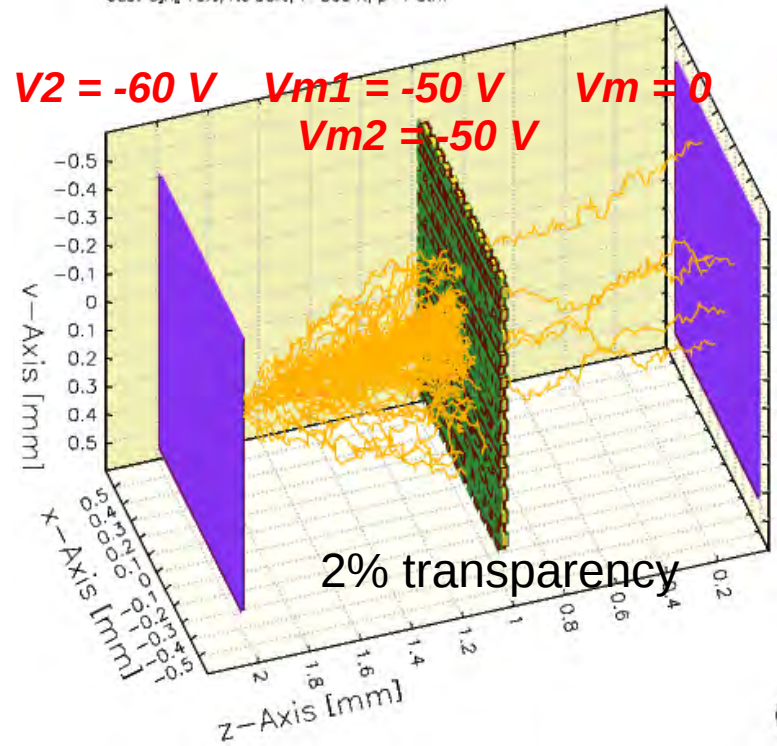
$V_2 = -60$ V $V_{m1} = -50$ V $V_m = 0$
 $V_{m2} = -45$ V



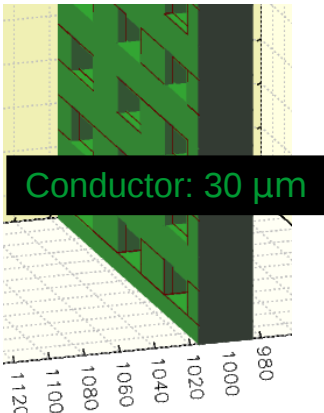
20% transparency

Gas: C_2H_6 10%, Ne 90%, $T=300$ K, $p=1$ atm

$V_2 = -60$ V $V_{m1} = -50$ V $V_m = 0$
 $V_{m2} = -50$ V

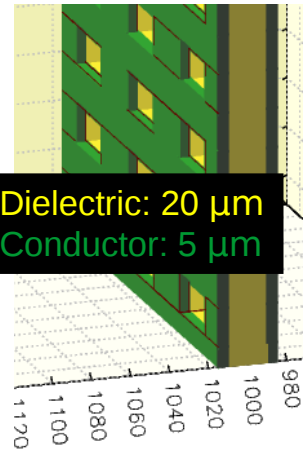


2% transparency



Conductor: 30 μm

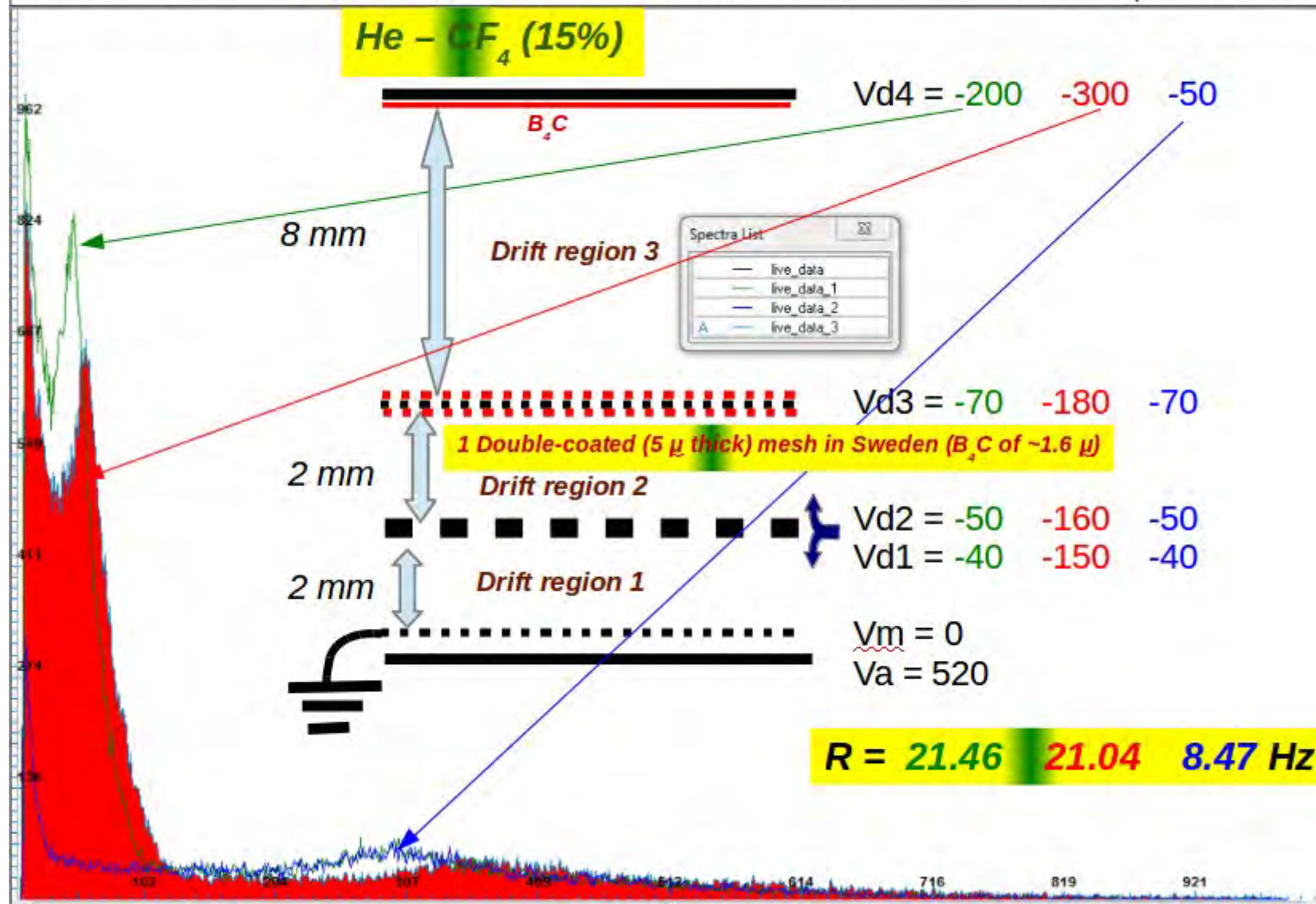
Box diam = 40 μm
Hole diam = 40 μm



Dielectric: 20 μm
Conductor: 5 μm

Box diam = 40 μm
Hole diam = 40 μm

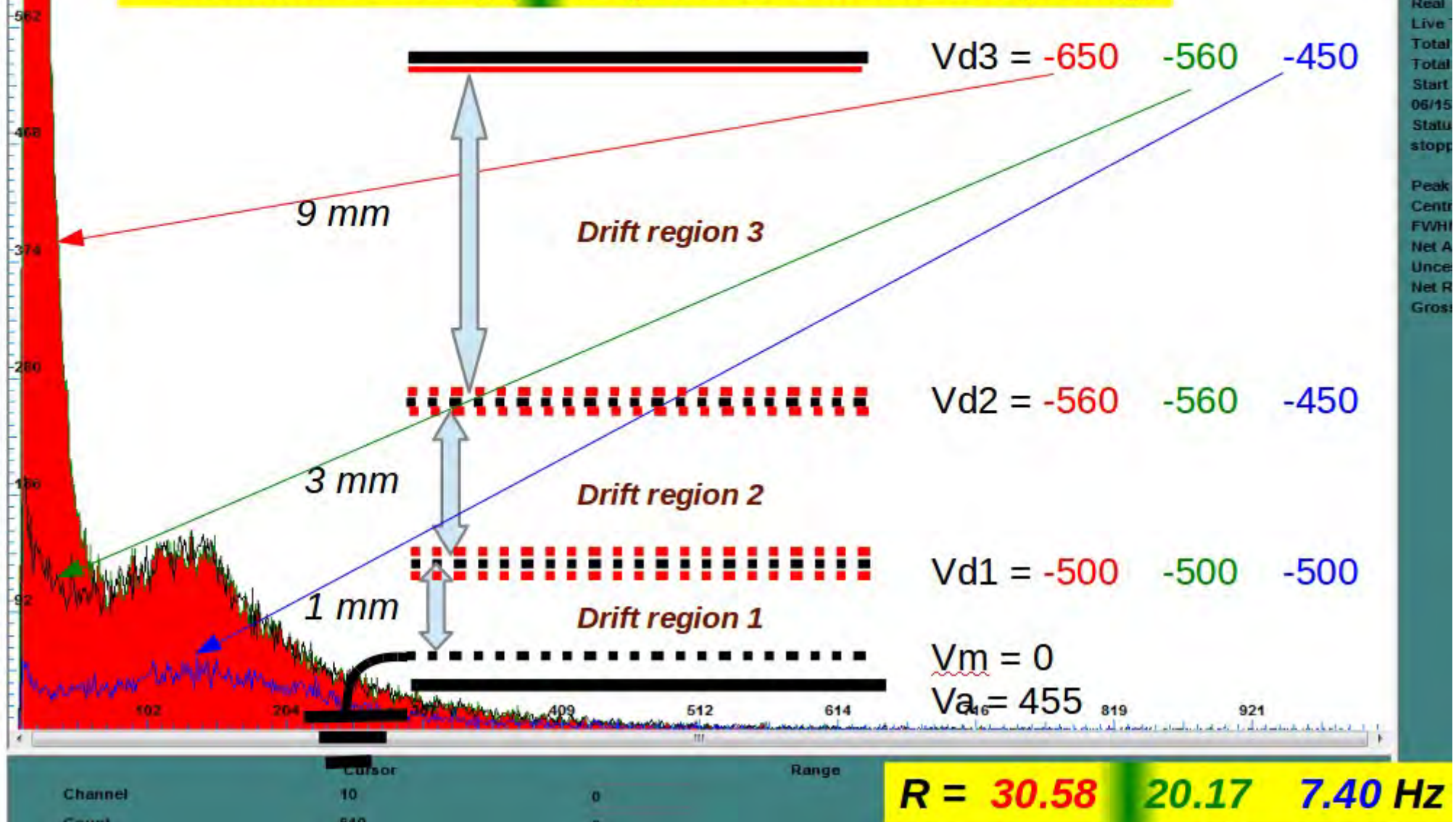
Using a GEM type mesh → 2 ind. V + 1 double coated B₄C mesh



Data measured during 3000 s for each run, combining an uncoated GEM type kapton mesh and a double coated Nickel mesh in the same set-up.

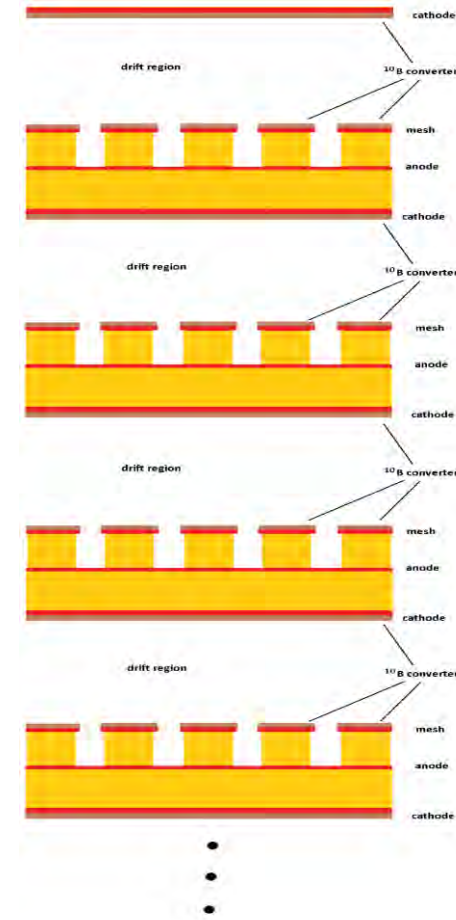
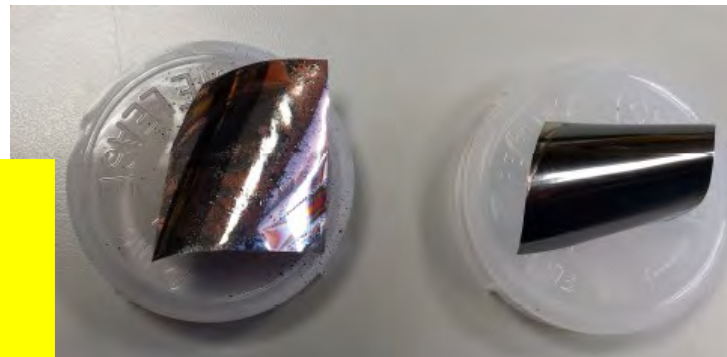
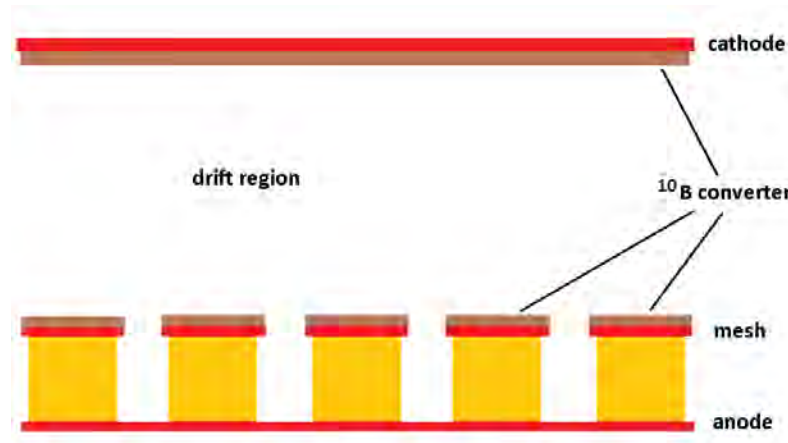
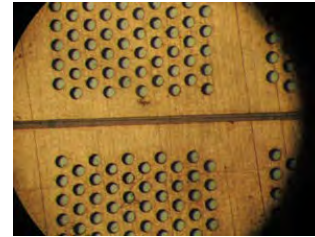
He - CF₄ (15%)

- 2 Double-coated (5μ thick) meshes in Sweden (~1.6 μ)



Data measured during 1500 s for each run, using a single 2-mesh detector unit equipped with 5 layers of B₄C.

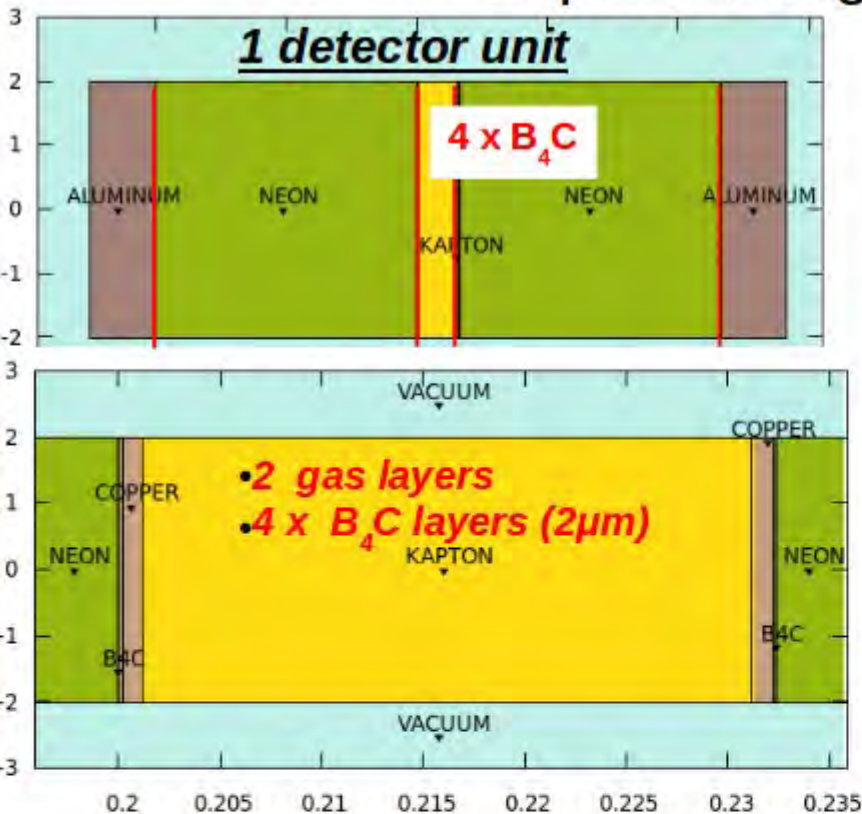
Alternative 2: Microbulk stack



- Microbulk is also a Kapton mesh, Cu-coated.
- Boron can be deposited on the Microbulk surface
 - double efficiency
 - Ni or Au coating needed
 - ✗ Same problem from thermal expansion coefficients
- Units can be stacked without limitation, using only 3 voltages (same cathode, mesh, anode voltages)
- ✓ Unit can be very thin (~1 mm)
- ✓ Low material budget
- ✓ Common / independent readout possible

- We have done some tests trying to deposit B_4C on Microbulk raw material.
- The deposition on the copper doesn't work, but on the Nickel coated copper it looks great, even after 2 months from the time the deposition was done.
- So, Nickel coated Microbulks seems it is the good way to proceed.

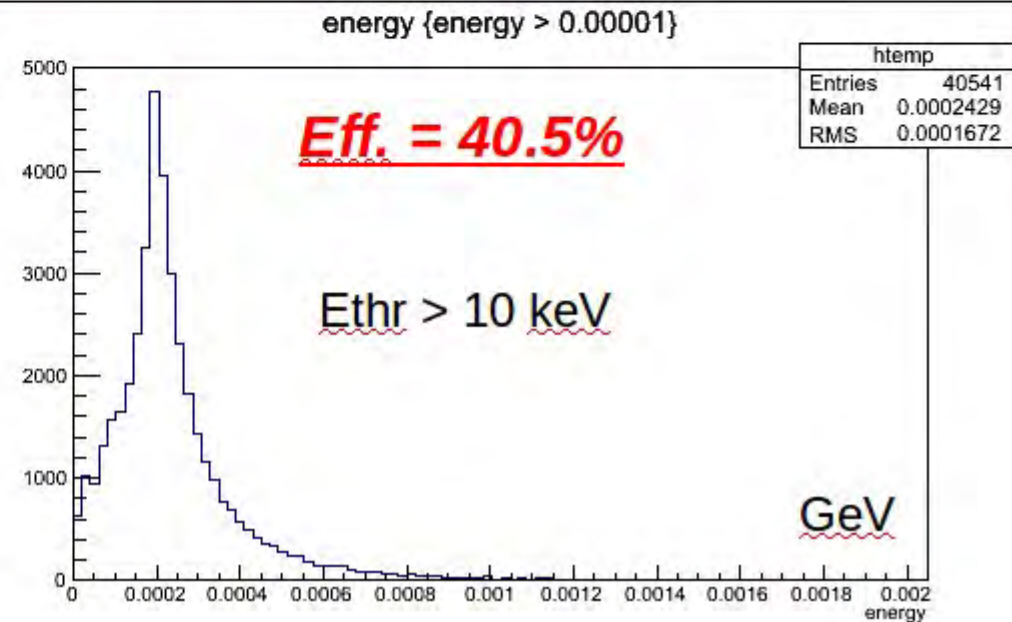
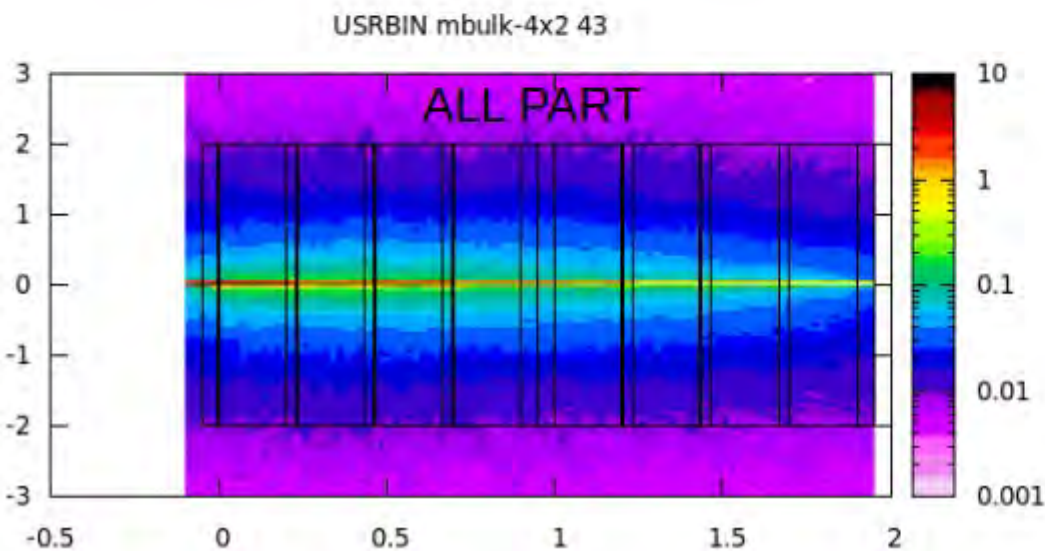
Implementing the microbulk technology



- 2 Al end plates 4 x 4 cm: 0.5 mm thick
- 2 Gas layer Neon: 2 mm thick
- 4 layers of converter B_4C : 2 μ m thick
- 1 Kapton layer: 300 μ m thick
- 2 Copper layers: 10 μ m thick

using FLUKA MC

- 2 x 4 detector units
- 8 gas layers
- 16 x B_4C layers (2 μ m)

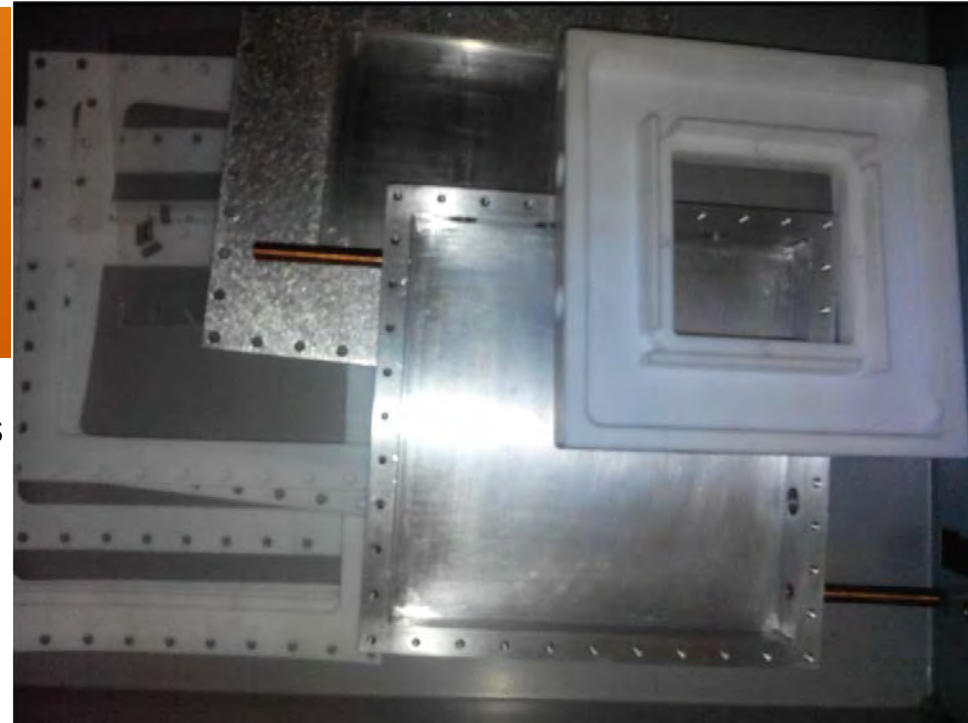


SINE2020 Work Program

Original idea :

Move to microbulk to have thinner PCB layer and enable the stacking of detectors to improve the detection efficiency

The ***main advantage of the microbulk*** detector is that there is no PCB and the readout pads are supported directly on 50 μm pillars which support the micromesh. Neutron scattering from such an arrangement should be very low and thus it should be possible to stack several layers one behind the other without adversely affecting the incoming neutrons.



- ***Micro-bulk micromegas*** → Novel geometry of large scale neutron detector: a mosaic of micro-bulk micromegas coated with $^{10}\text{B}_4\text{C}$.
- ***Simulations***: of first concept by placing 4 back-to-back microbulk micromegas detector units, the neutron efficiency is 40%
- ***A prototype*** was designed and built: a modular $15 \times 15 \times 2 \text{ cm}^3$ chamber in which up to 4 kapton micro-bulk micromegas can be stacked
- ***Tests to deposit B_4C*** on Micro-bulk raw material are on going
- ***Simplified concept : Start testing*** of a prototype where mesh is replaced by micro-bulk layer

Outlook

- New meshes of kapton with/without frame are ordered from CERN
- Use of a mesh like a mask in front of the kapton mesh for achieving the deposition in little rectangles (islands) and not uniform, hoping there will be no problems with the thermal expansion
- Low power deposition with sputtering without heating
- Plasma/Ar cleaning of kapton mesh before coating to avoid oxidation
- New simulations with Nebem/garfield 3D are planned taking into account this time the GEM type mesh where 2 independent voltages can be applied on top/bottom, and estimate the transmission of electrons for different gases.

Summary

We are examining possible ways to increase the detection efficiency for thermal neutrons, using solid neutron-to-charge convertors:

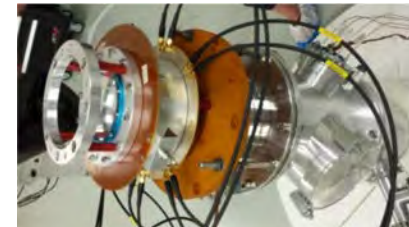
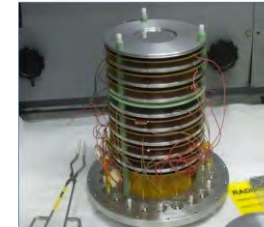
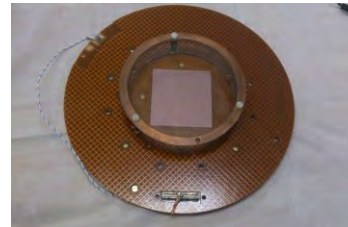
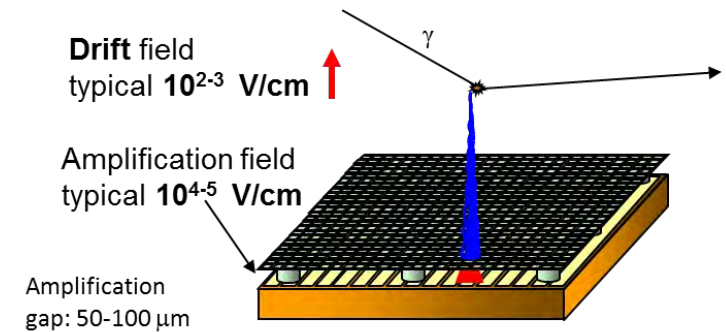
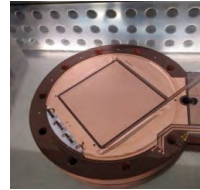
- A Micromegas equipped with several metallic (Ni) thin meshes coated with B_4C in both sides
 - ✓ Efficiency improvement as expected by the simulations
 - × Small electron transmission for thick (robust) meshes
 - × Deformation & fragility for thin meshes. Problem for large surface detectors
- A Micromegas equipped with GEM-type meshes coated with B_4C in both sides
 - ✓ Good electron transmission. Amplification during transmission easy
 - ✓ Small voltages
 - ✓ Robustness. Large surface detectors possible with low cost
 - × Deposition of B_4C on the foil is difficult. Under study
- A stack of Microbulks coated with B_4C
 - ✓ Low material, thin detector
 - × Deposition of B_4C on the foil is difficult. Under study.

Back-up slides

Micromegas R&D

Experiments @ CERNs: New detectors & Continuous improvement

- CAST
 - ▢ Microbulk development
- nTOF
 - ▢ Microbulks for flux measurements
 - ▢ Microbulks for fission measurements
 - ▢ XY-Microbulk

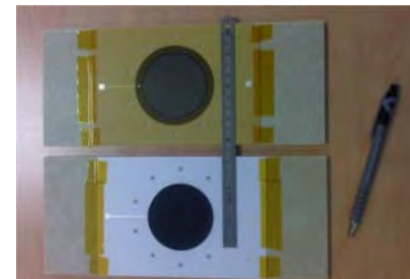
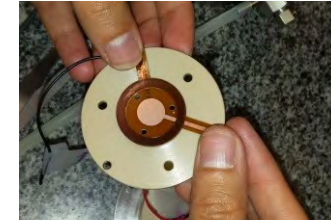
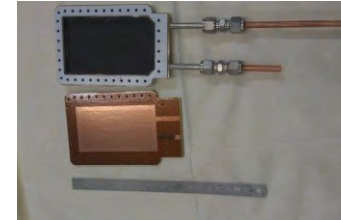
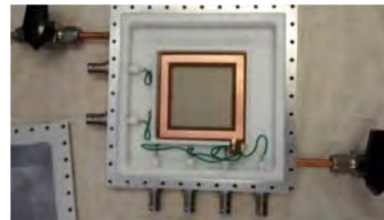


R&D for other projects

- NMI3
- Schlumberger
- Picosecond

Detector technology R&D

- Piggyback
- Thin mesh
- Kapton mesh
- XY-Microbulk
- Small gap Microbulk
- Resistive Micromegas



Micromegas R&D

People involved at SEDI



eferrer

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DSM//IRFU/SEDI/DEPHYS
Service d'Electronique, des

- Chef de laboratoire
- Chef de projet
- Membre du CSTS



ioa

Ioannis GIOMATARIS

DSM//IRFU/SEDI/DEPHYS
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- Responsable scientifique



attie

David ATTIE

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- Membre du CU du service
- Membre du CSTS



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aunes

Stephan AUNE

DSM//IRFU/SEDI/DIR
Service d'Electronique,

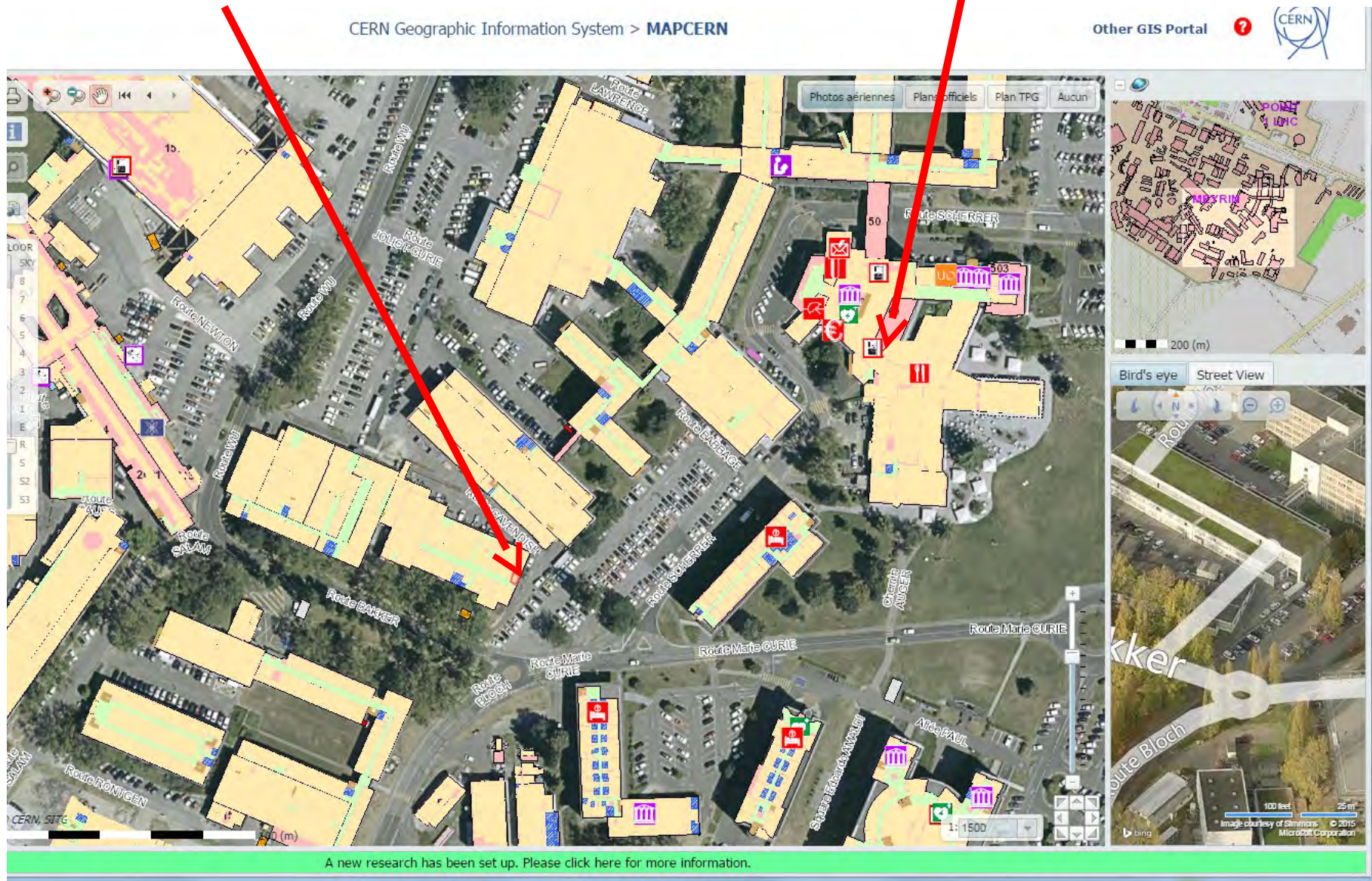
- Chef de projet

+ Fabian Jeanneau, Alan Peyaud, George Tsiledakis, Paul Serrano, Mariam Kebbiri...

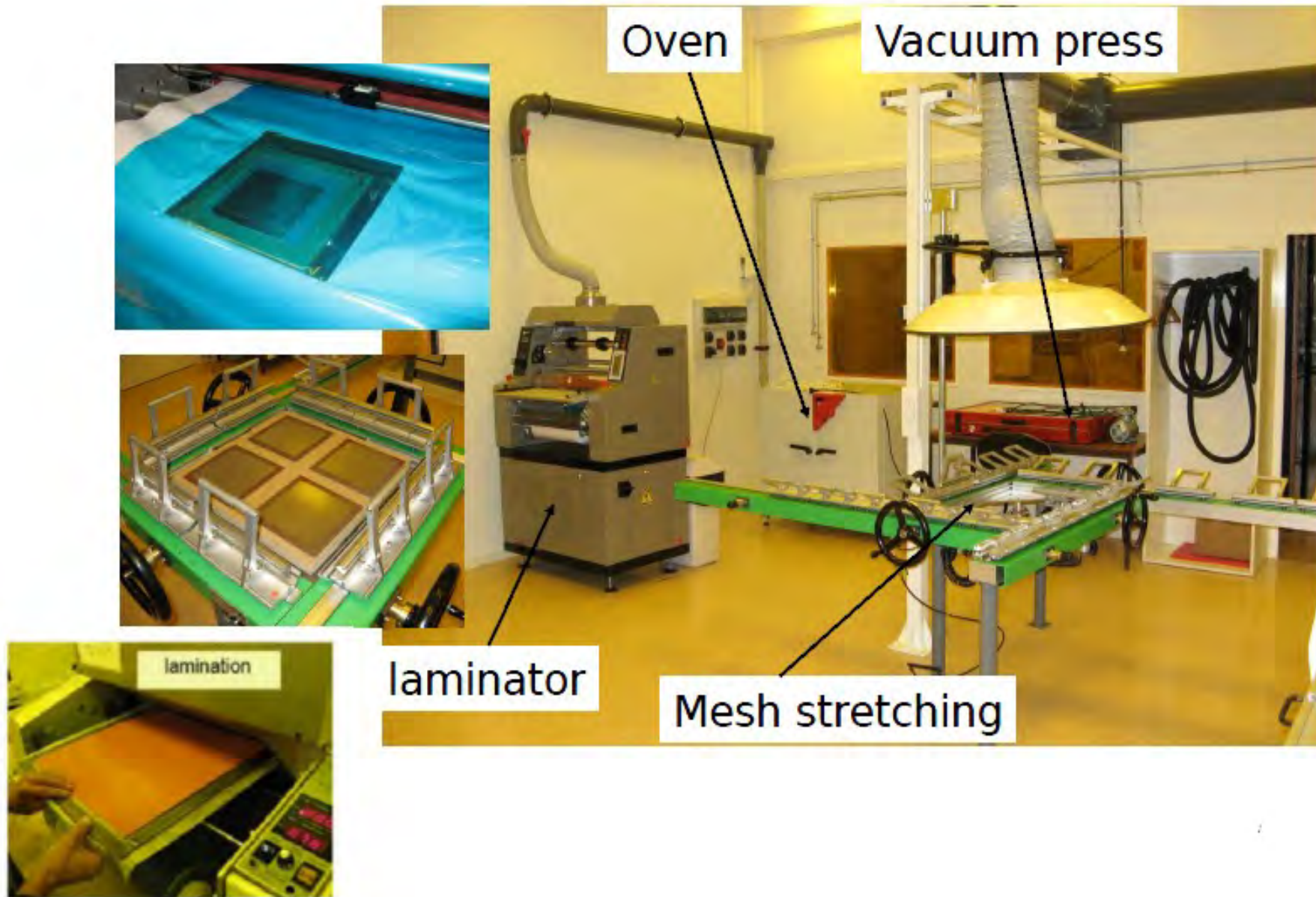
Micromegas R&D

Close collaboration with the detector Lab
of **De Oliveira, Rui** [PH-DT-DD 102/R-018](#)
tel: [73745](#) [163931](#) (Rui.de.Oliveira@cern.ch)

Main building – R1



The bulk lab @ SEDI, CEA Saclay



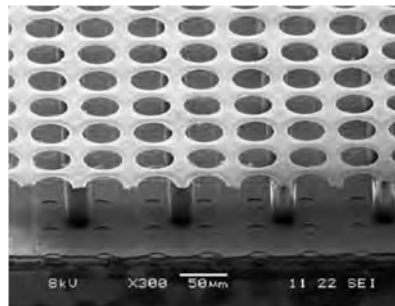
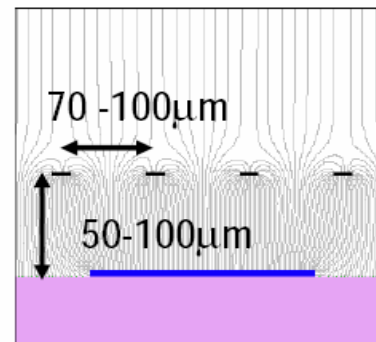
Micro Pattern Gaseous Detectors (MPGD)

Best technology for gaseous detector readout:

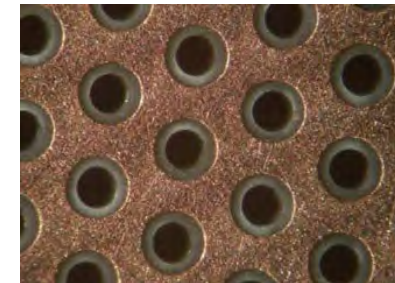
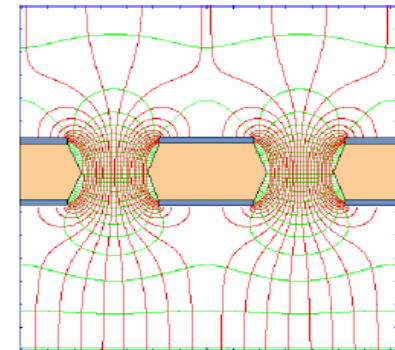
Micro Pattern Gaseous Detectors

- high granularity
- more robust than wires
- no $E \times B$ effect
- fast signal & high gain
- low ion feedback
- better ageing properties
- easier to manufacture
- lower cost
- big surfaces

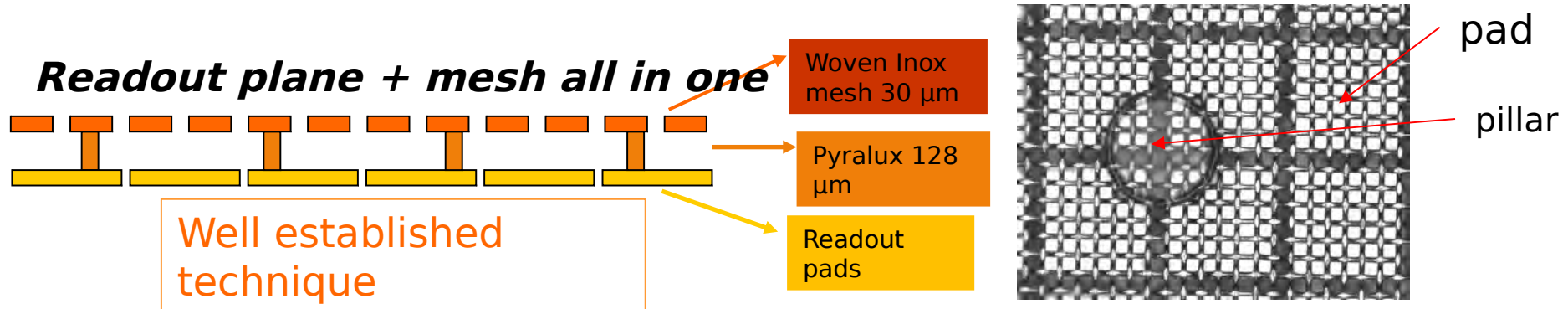
Micromegas



GEMs



Bulk Micromegas technology

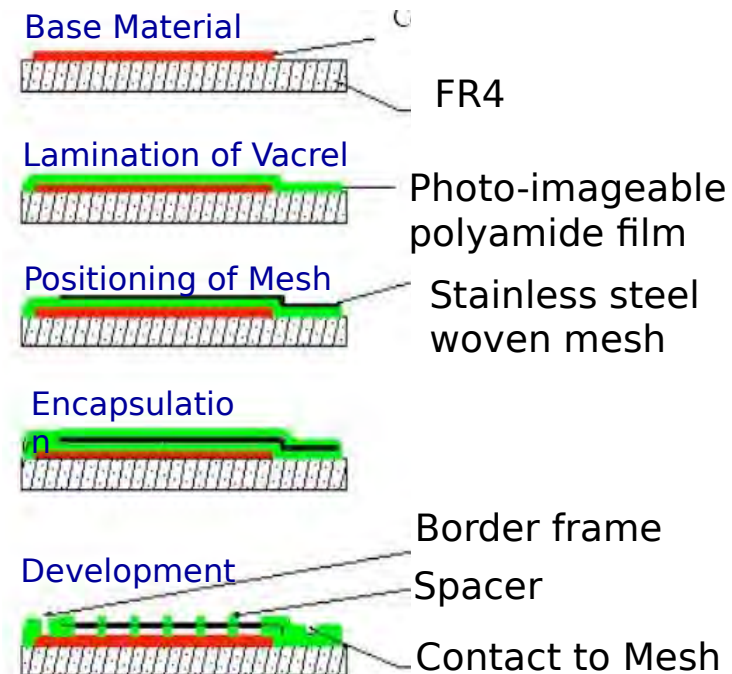


Result of a CERN-Saclay collaboration (2004)

Process to encapsulate the mesh on a PCB (mesh = stretched wires)

Motivations for using bulk Micromegas
the mesh is held everywhere:

- the mesh is held everywhere
- robustness (closed to dust)
- can be segmented
- repairable
- **large area detectors feasible and robust!**

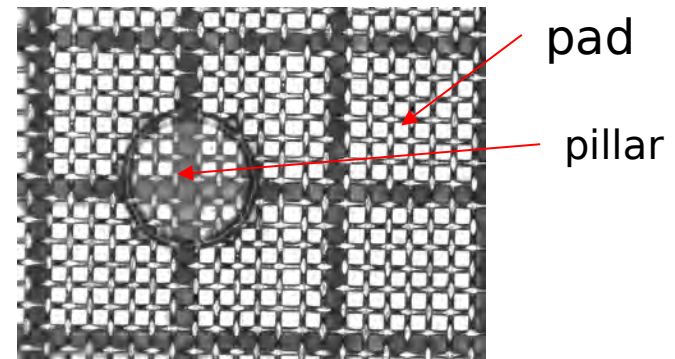


I. Giomataris *et.al.*, NIM A560 (2006) 405

Bulk Micromegas technology

Bulk Micromegas: The pillars are attached to a woven mesh and to the readout plane

Typical mesh thickness 30 μm , gap 128 μm

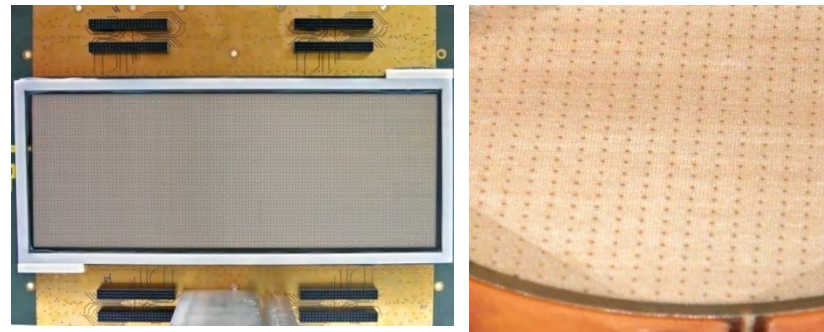
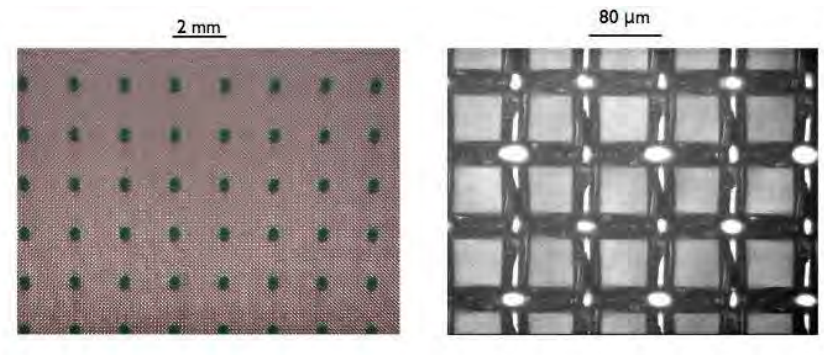


Uniformity, robustness, lower capacity, easy fabrication, no support frame, small surrounding dead region □

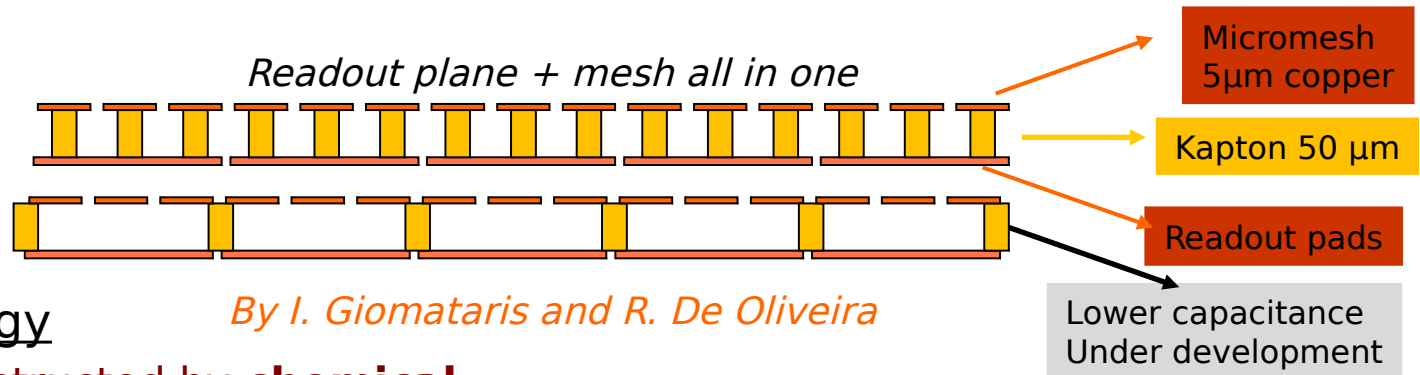
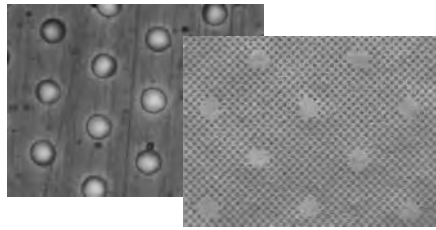
- ✓ **Large area detectors feasible and robust!**
- ✓ **Curved surfaces**
- ✓ Mass production!

Mesh thickness & bigger gap: some disadvantages in special applications:

- ✗ Good but limited energy resolution ($\sim 18\%$ @ 6keV)
- ✗ Restrictions on materials



Microbulk Micromegas technology



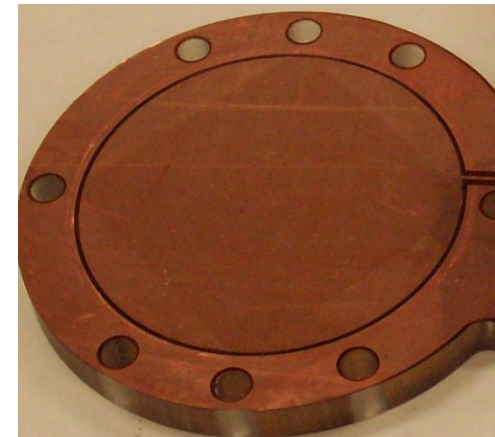
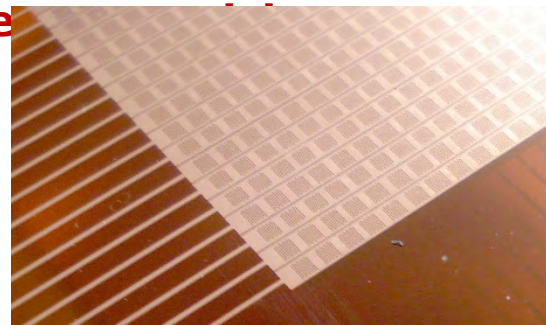
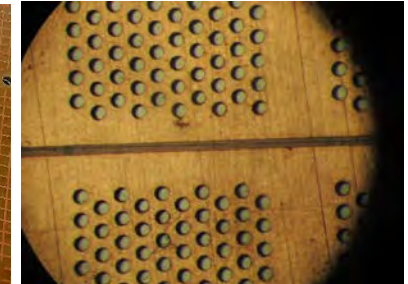
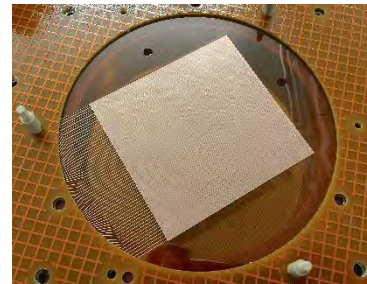
By I. Giomataris and R. De Oliveira

Microbulk Technology

The pillars are constructed by **chemical processing** of a **kapton foil**, on which the mesh and the readout plane are attached. **Mesh is a mask for the pillars!**

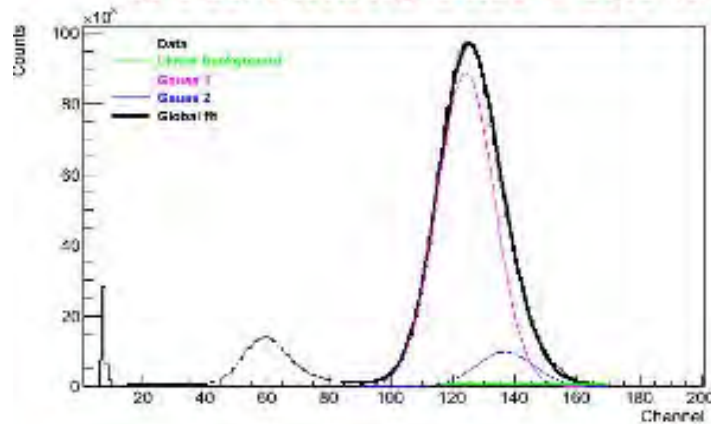
Typical mesh thickness 5 µm, gap 50/25 µm

- ✓ **Energy resolution** (down to 10% FWHM @ 6 keV)
- ✓ **Low intrinsic background & background recognition**
- ✓ **Low mass detector**
- ✓ **Very flexible structure**
- ✓ **Long term stability**
- ✗ Higher capacity
- ✗ Fabrication process complicated
- ✗ Fragility / mesh can not be replaced

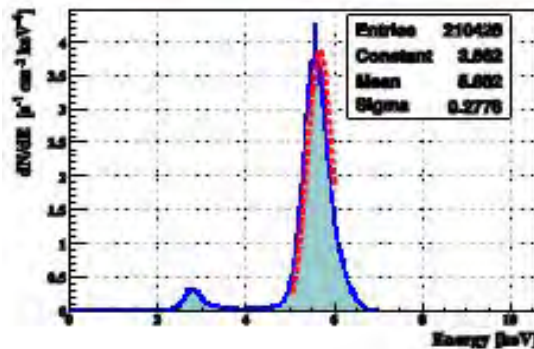


Energy and spatial resolution & stability

Bulk: 55Fe Calibration with Ar - 5% isobutane
@ 1 bar FWHM @ 6 keV = 17.6 %

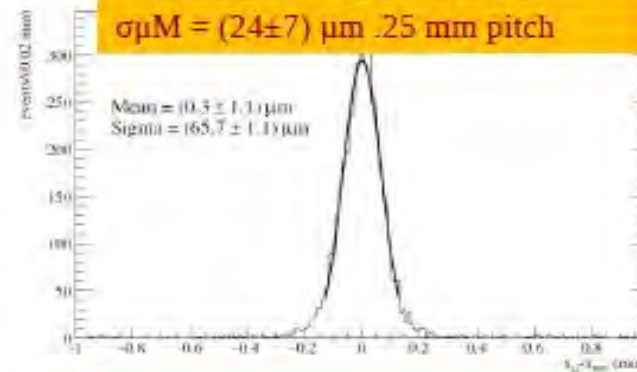


Microbulk: 55Fe Calibration with Ar - 5% isobutane
@ 1 bar FWHM @ 6 keV = 11.5 %

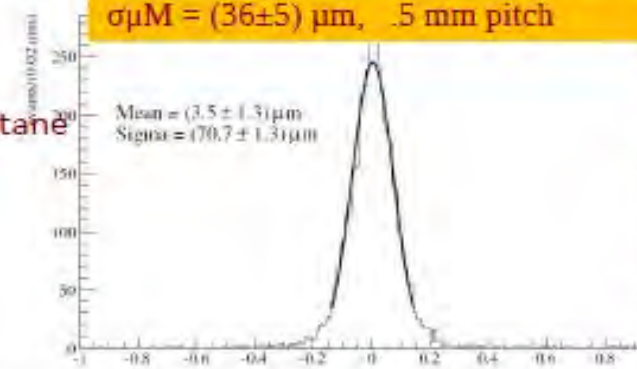


Bulk: Spatial resolution measurements for the MAMA project (sLHC)

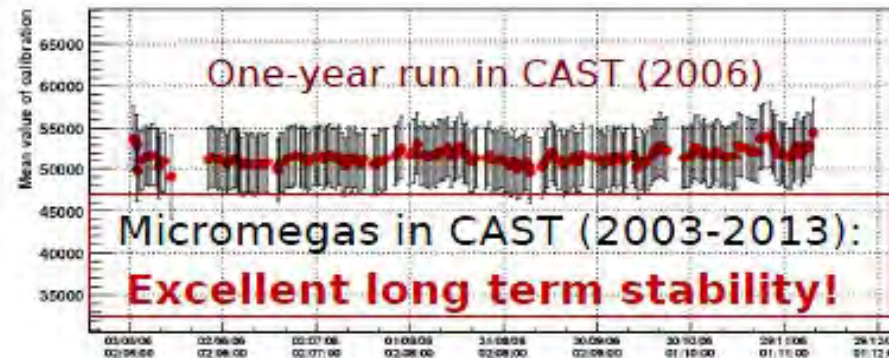
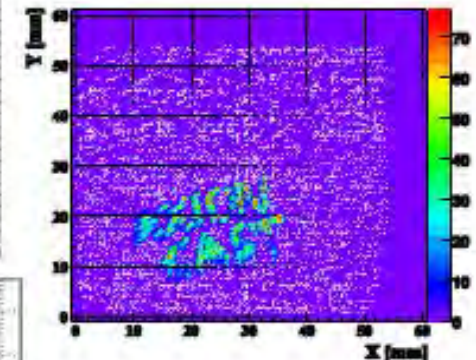
$\sigma_M = (24 \pm 7) \mu\text{m}$.25 mm pitch



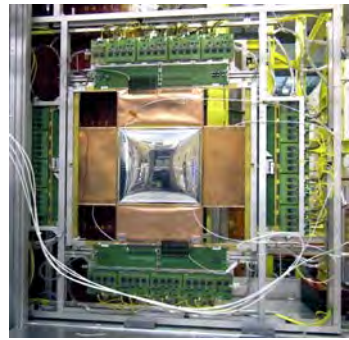
$\sigma_M = (36 \pm 5) \mu\text{m}$.5 mm pitch



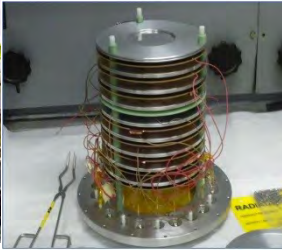
Microbulk: Image taken using a collimator with the words "axion cast"



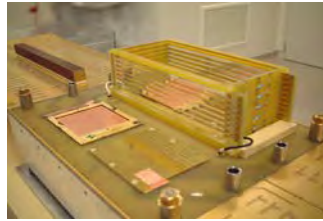
Micromegas applications



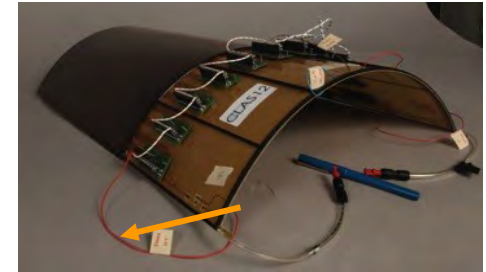
COMPASS NTOF



KABES/NA48



MINOS



CLAS12

1996

2000

2001

2003

2009

2014

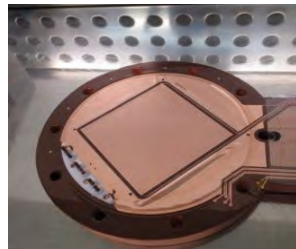
2015

2018

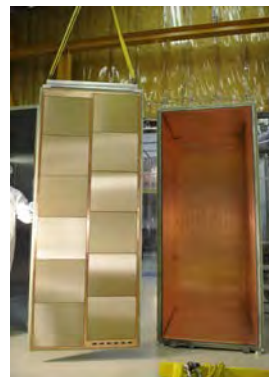


Micromegas
Invention

CAST



T2
K



ATLAS-

